

FIG. 1A

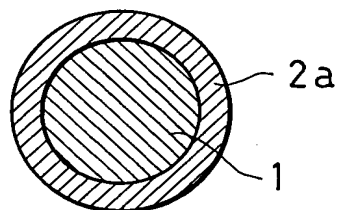


FIG. 1B

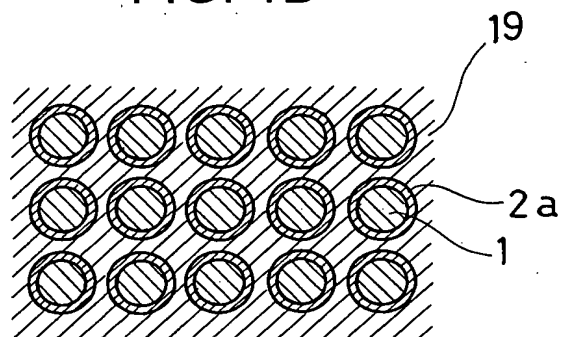


FIG. 1C

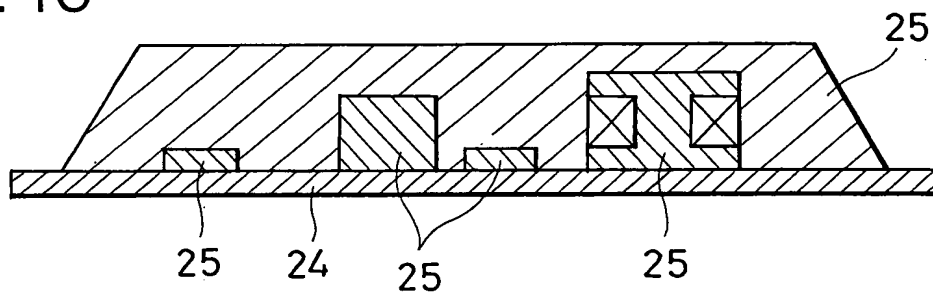


FIG. 1D

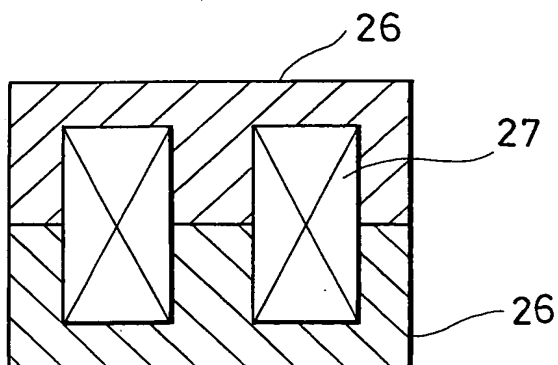
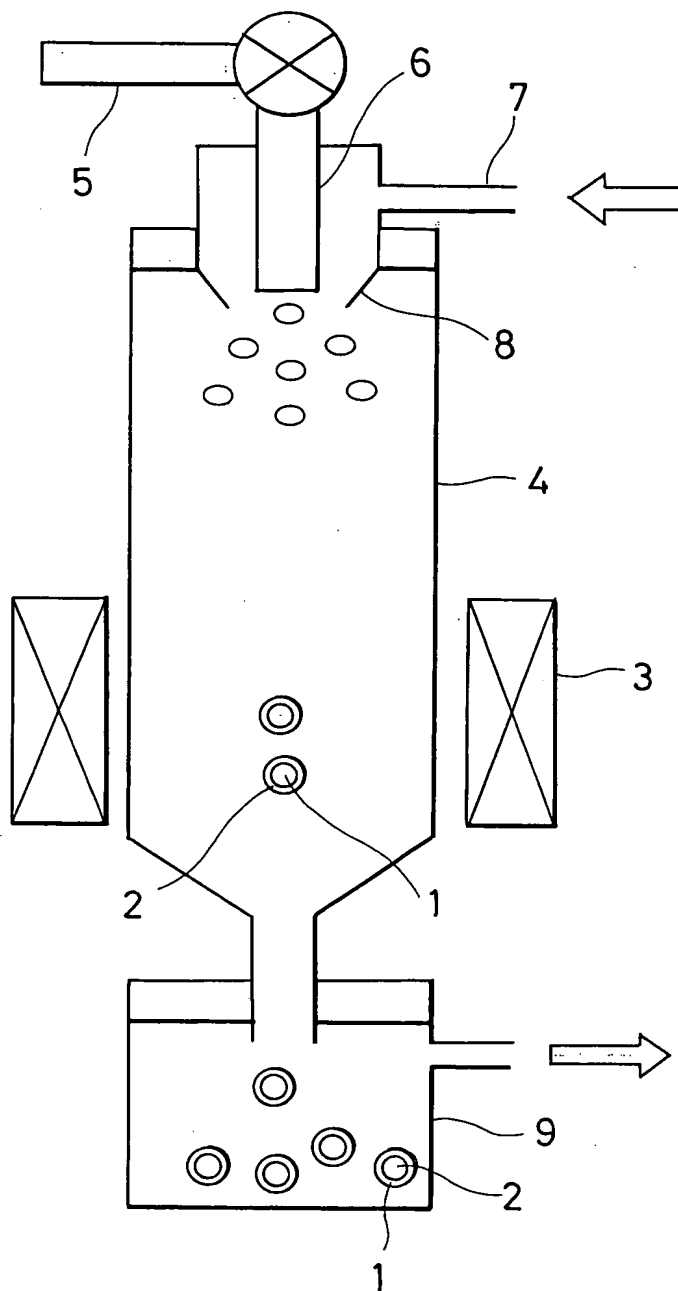


FIG. 2



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FIG. 3A

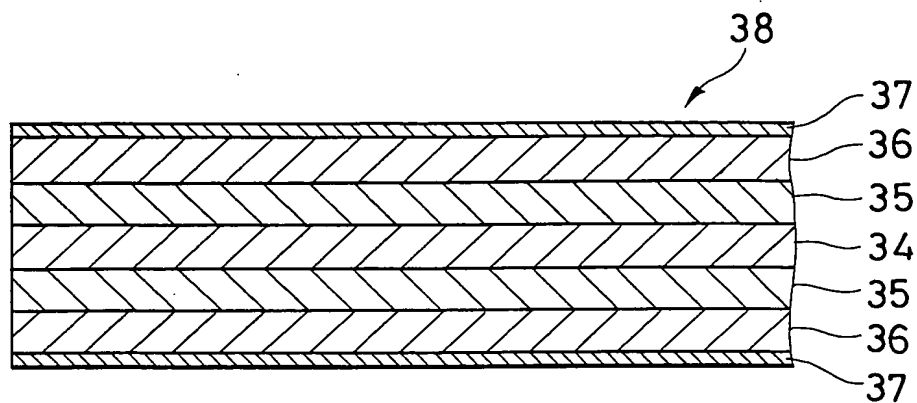


FIG. 3B



00922T" 00864260

FIG. 4A

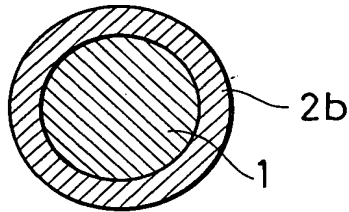


FIG. 4B

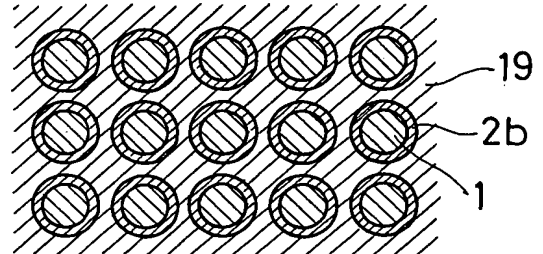


FIG. 4C

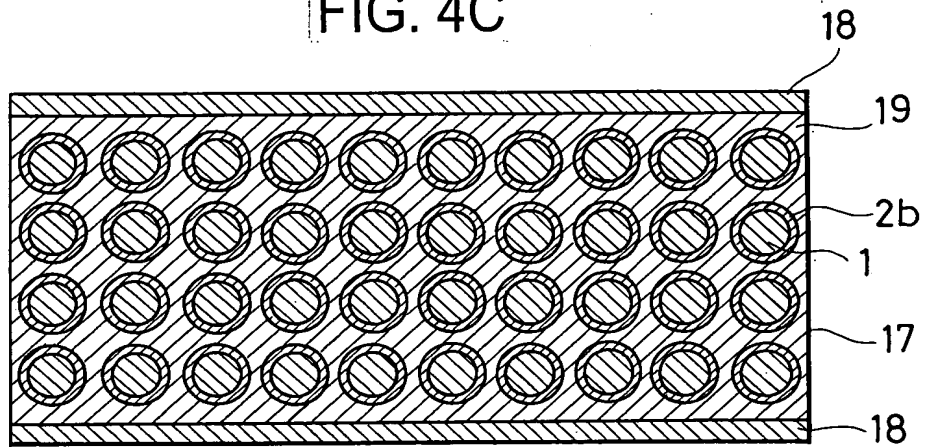
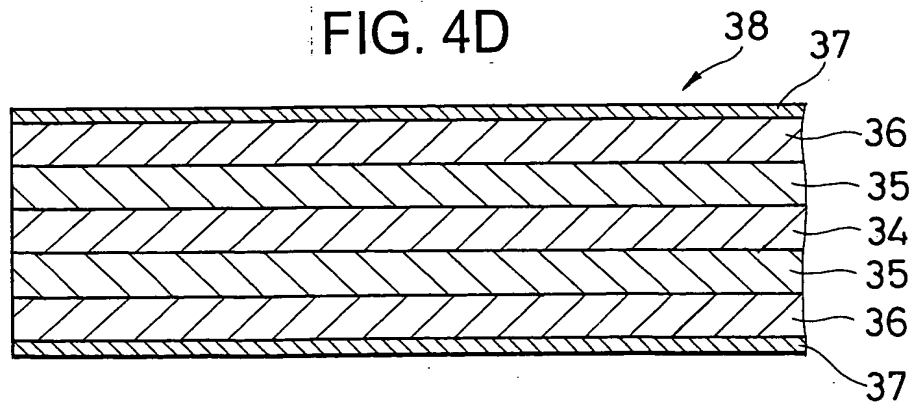


FIG. 4D



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FIG. 5A

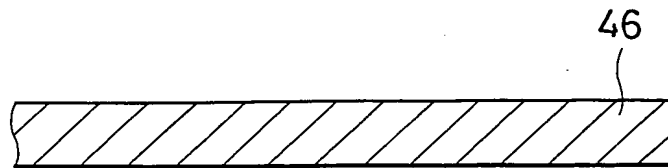


FIG. 5B

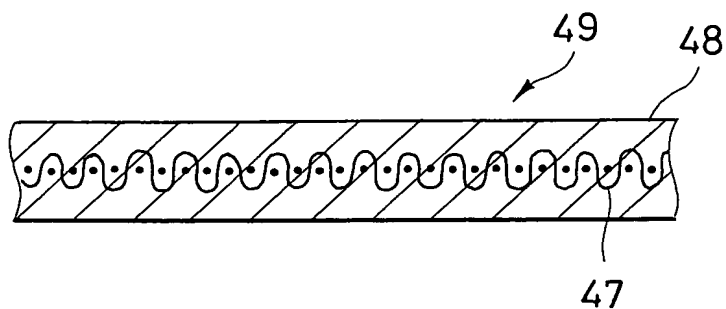


FIG. 5C

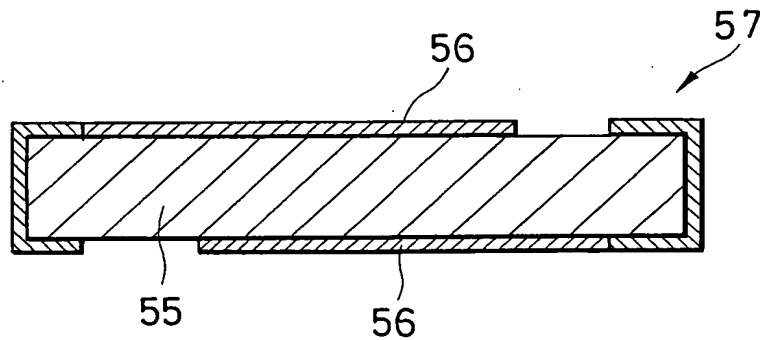
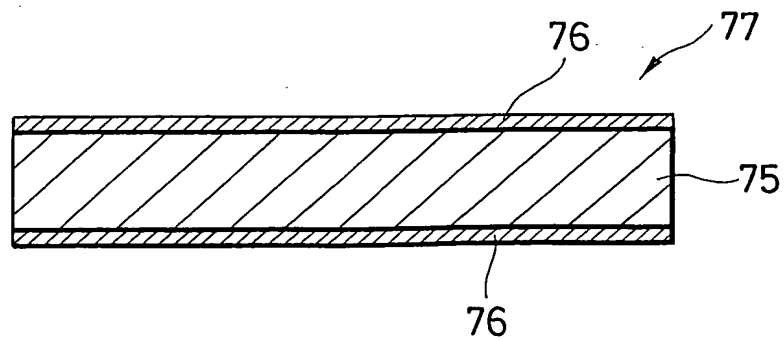
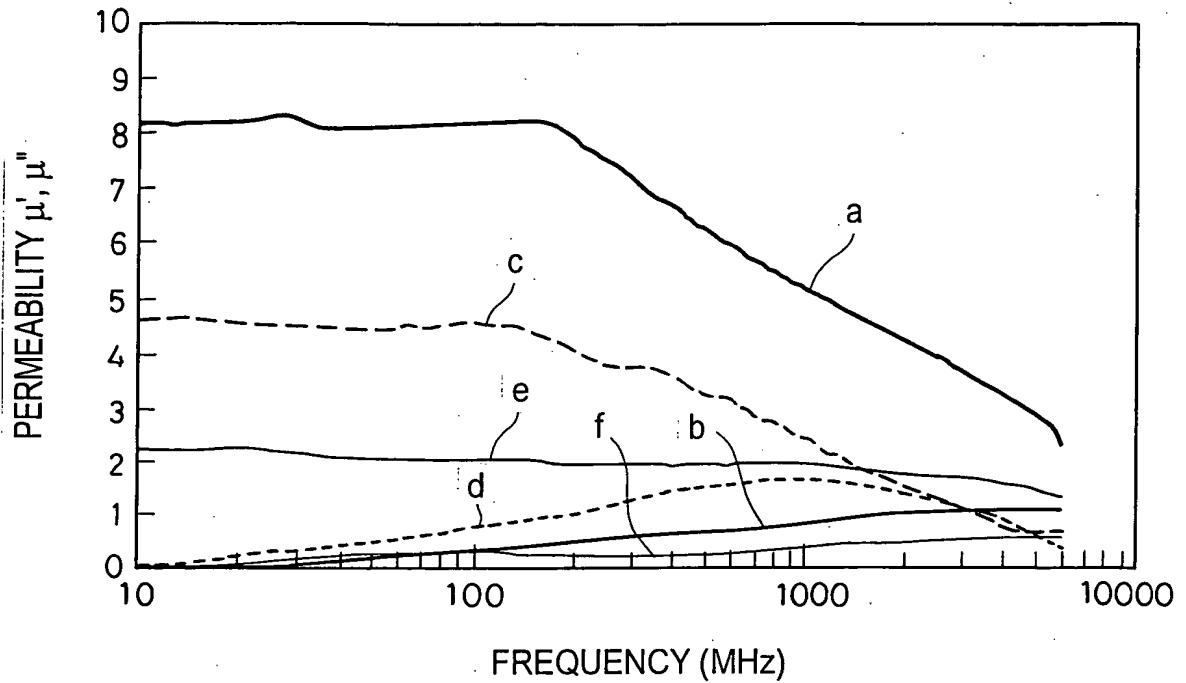


FIG. 5D



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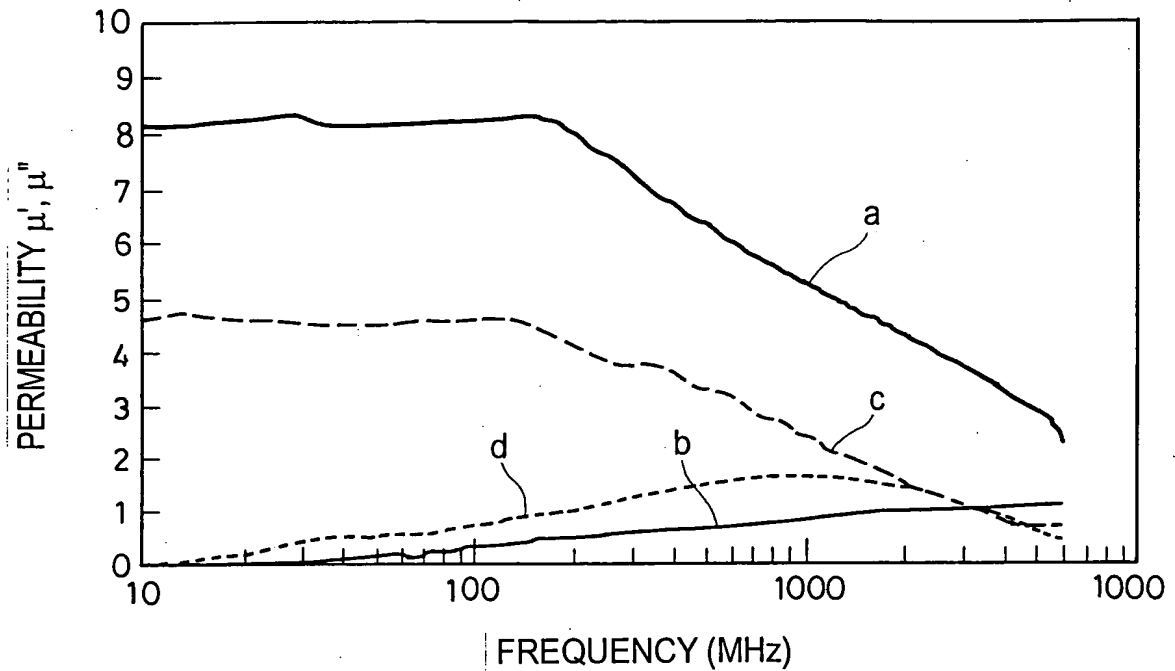
FIG. 6



- a: INVENTION, μ'
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- e: COMPARISON 2, μ'
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL
- f: COMPARISON 2, μ''
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL

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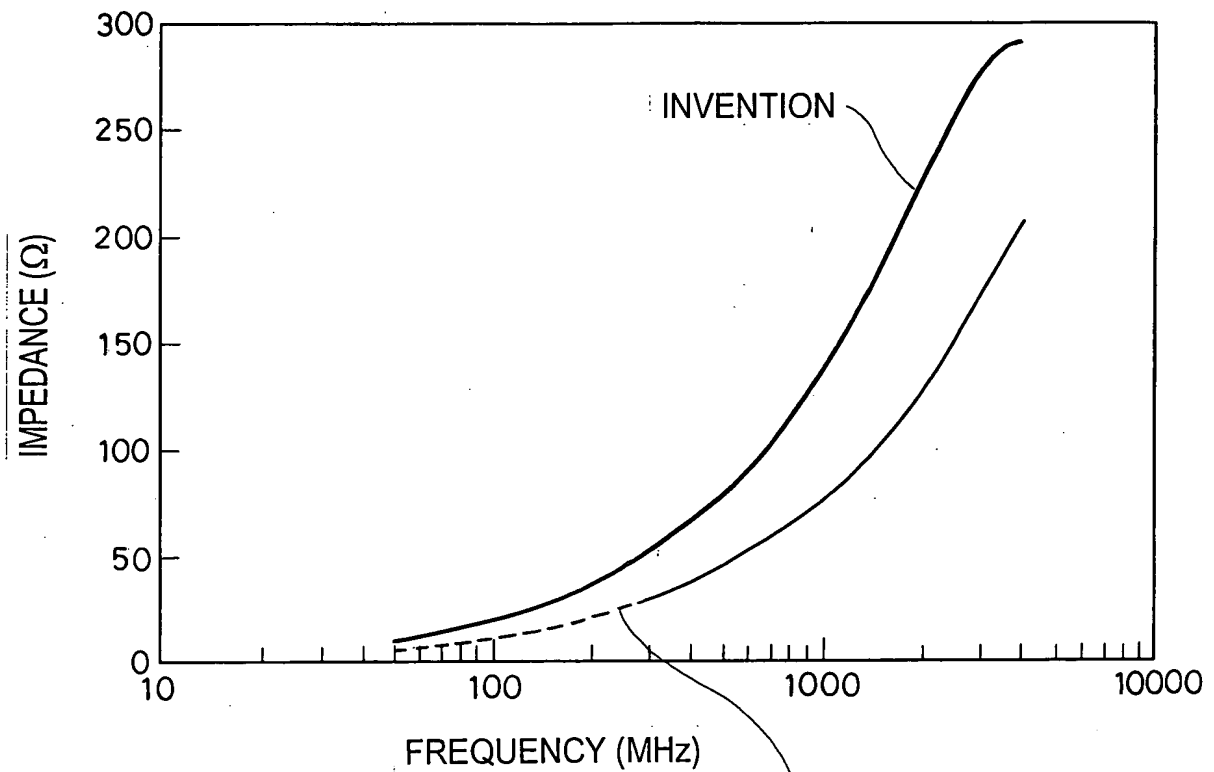
FIG. 7



- a: INVENTION, μ'
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL

008221-00864650

FIG. 8



COMPARISON (HIGH-FREQUENCY BEADS USING FERRITE
COMPOSITE MAGNETIC SUBSTRATE)

008221" 00864260

FIG. 9

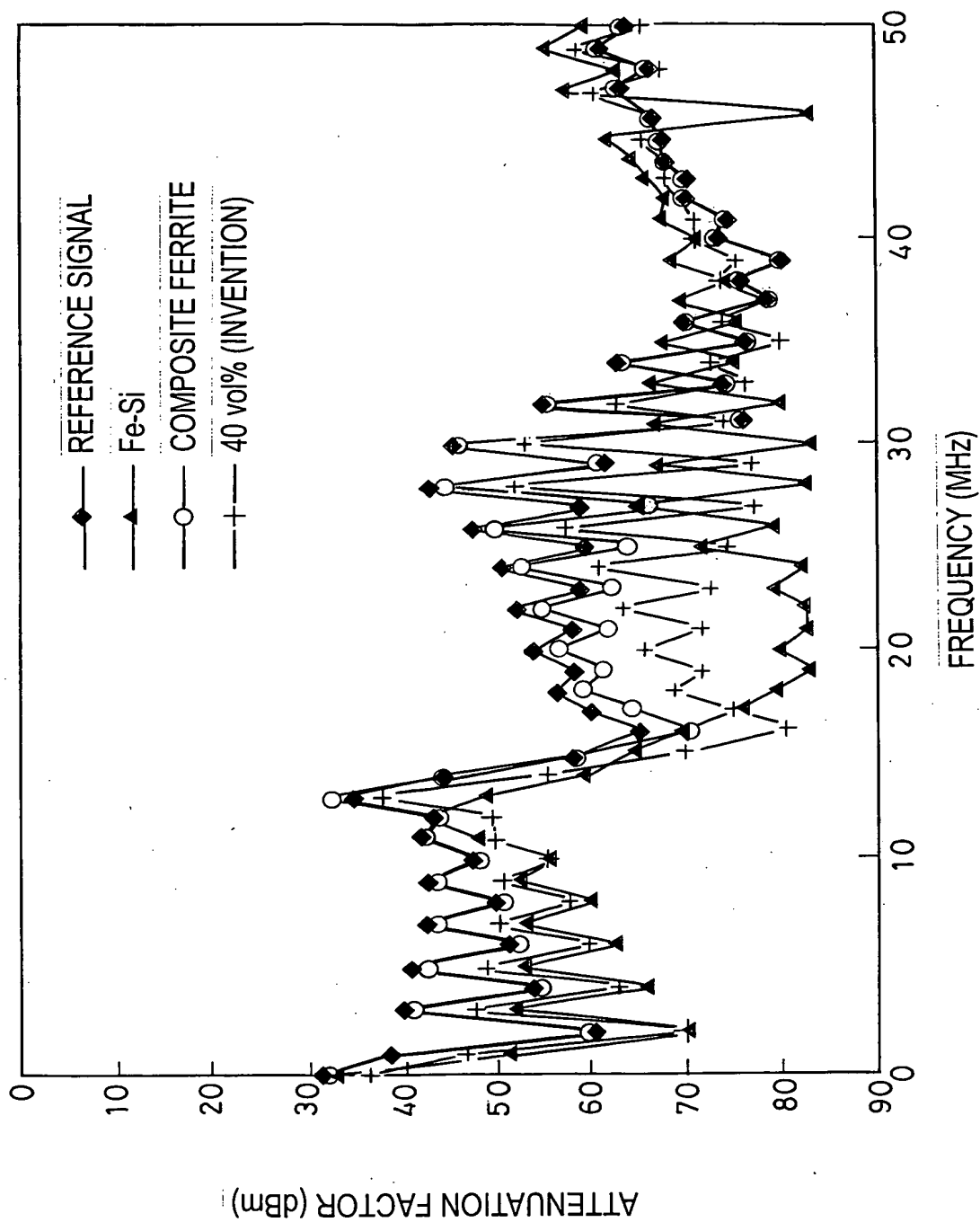
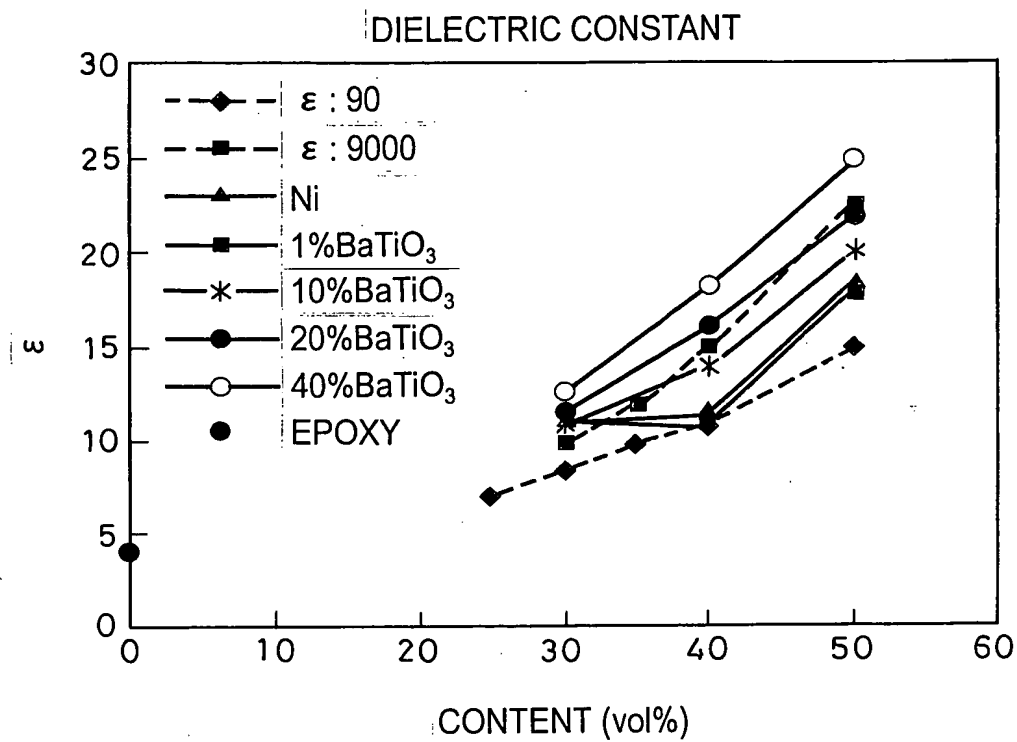
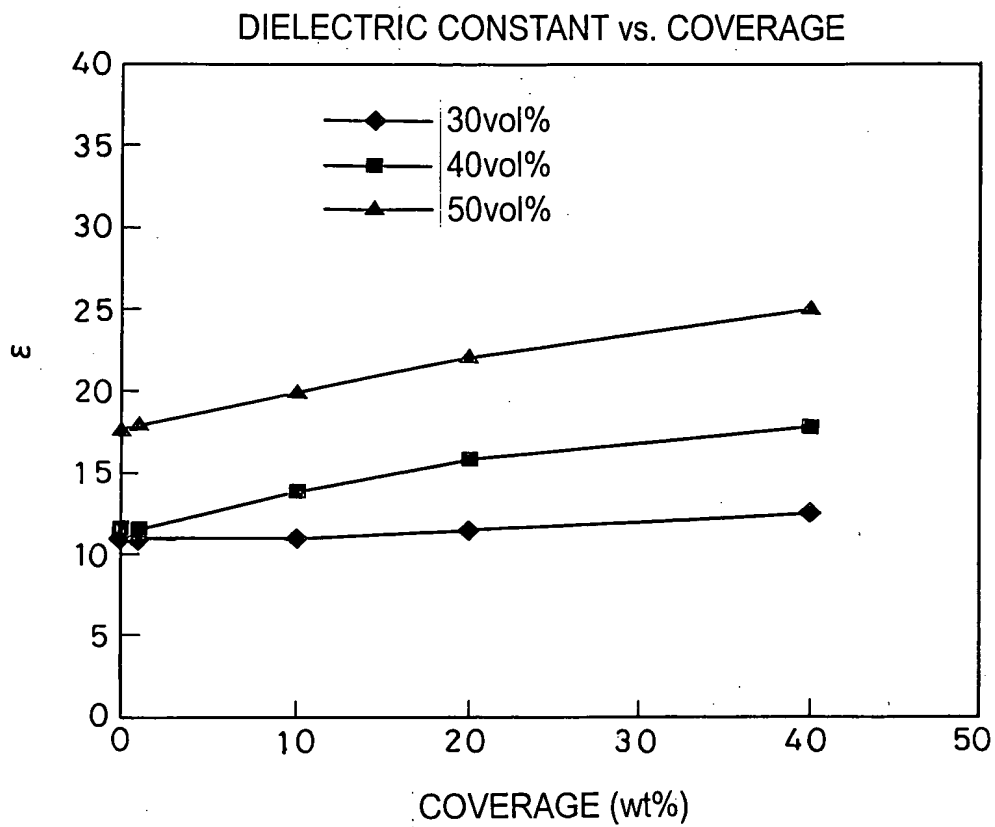


FIG. 10



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FIG. 11



09749800-122800

FIG. 12

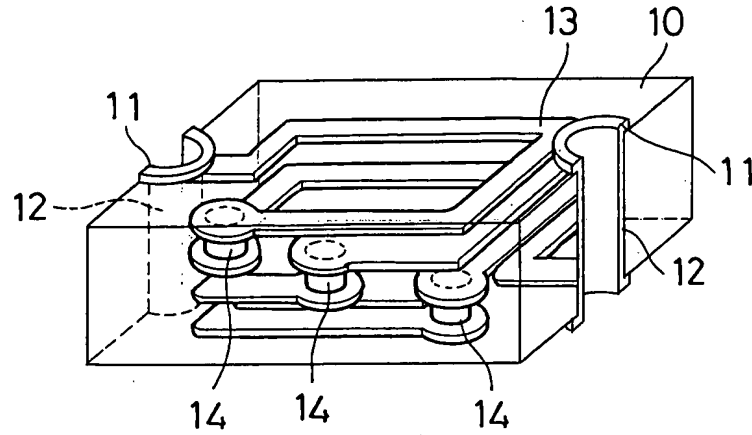
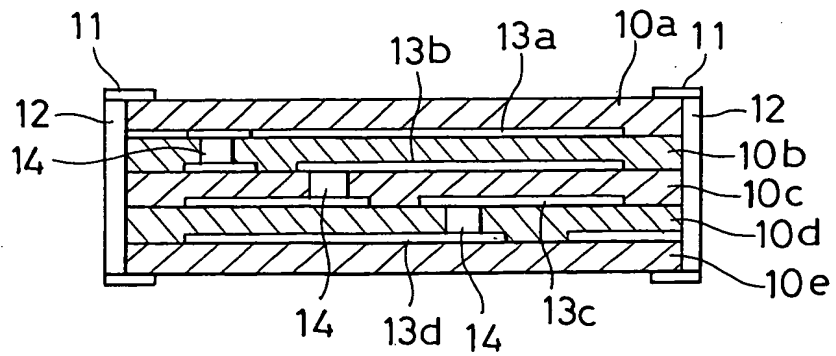


FIG. 13



00822T" 00864260

FIG. 14

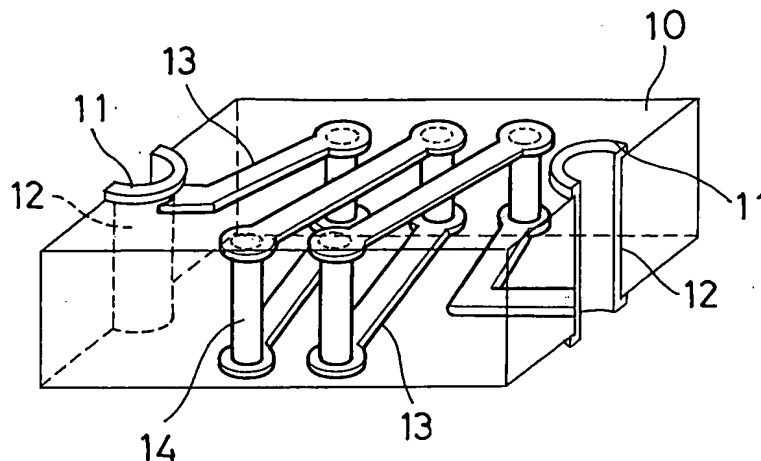


FIG. 15

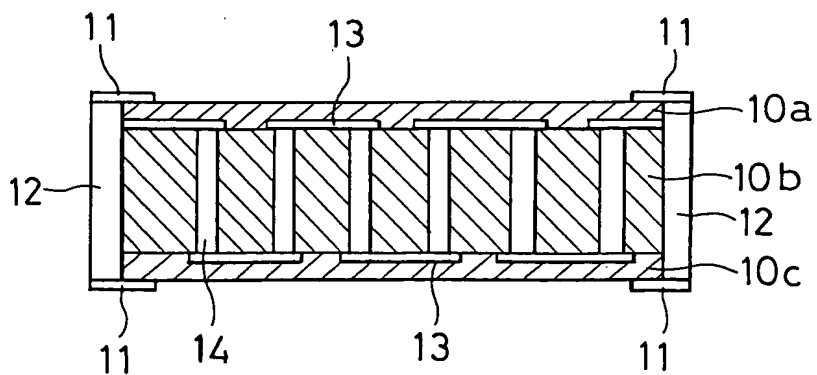


FIG. 16

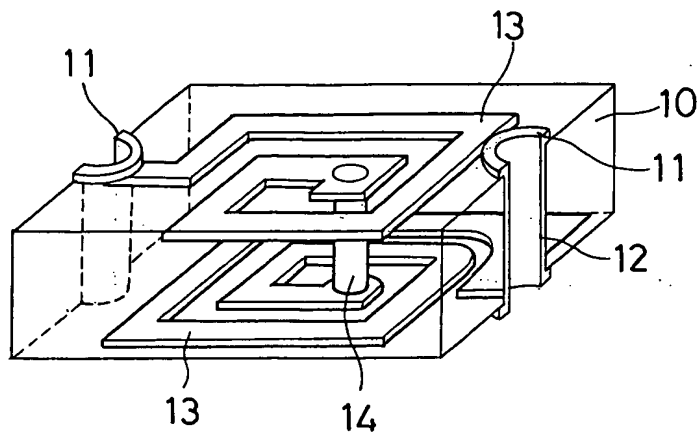
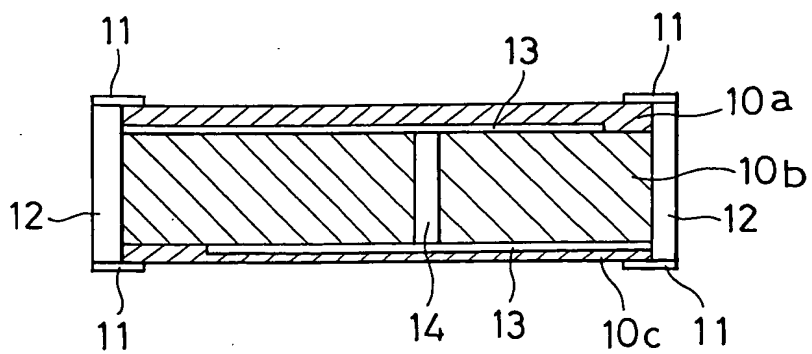


FIG. 17



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FIG. 18

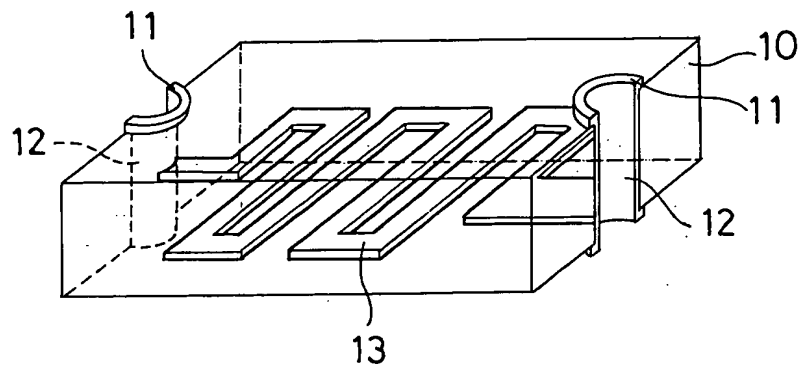
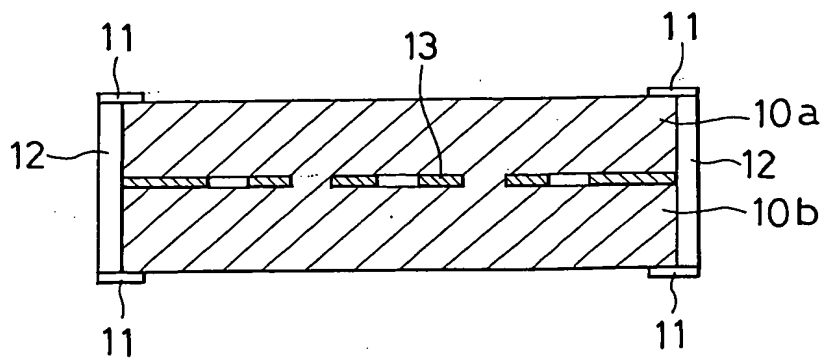


FIG. 19



00822T" 00864260

FIG. 20

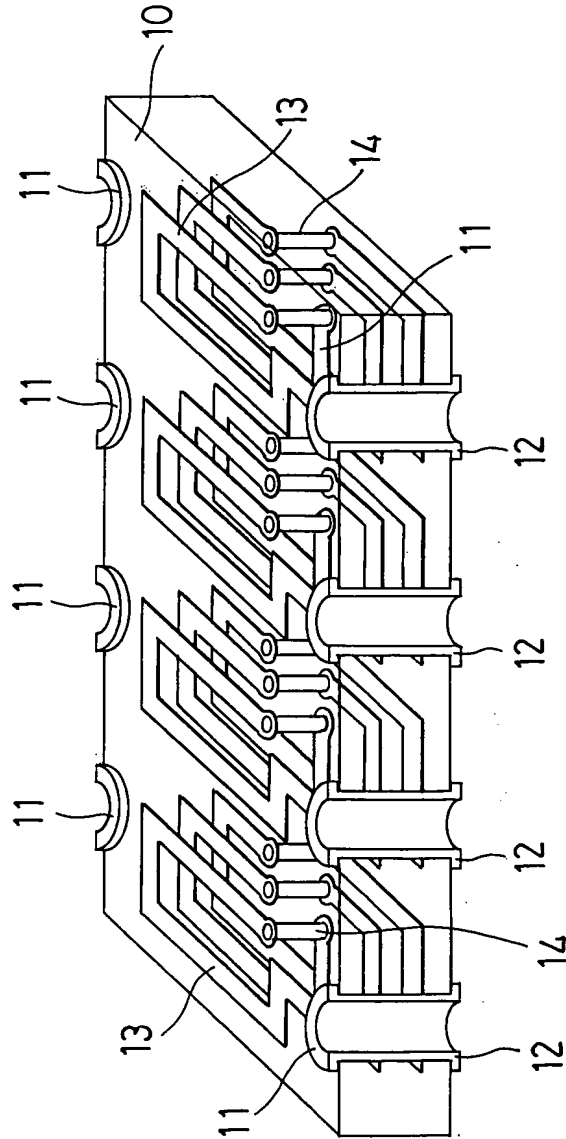


FIG. 21A

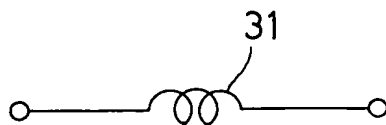


FIG. 21B

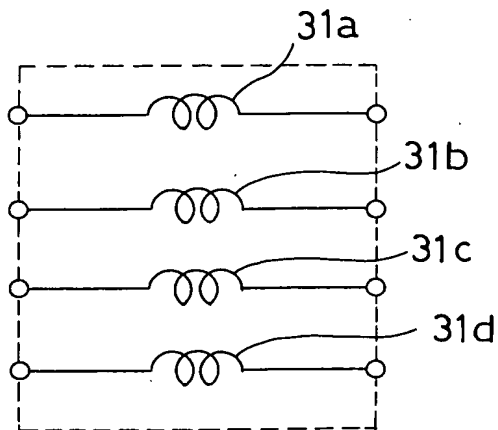
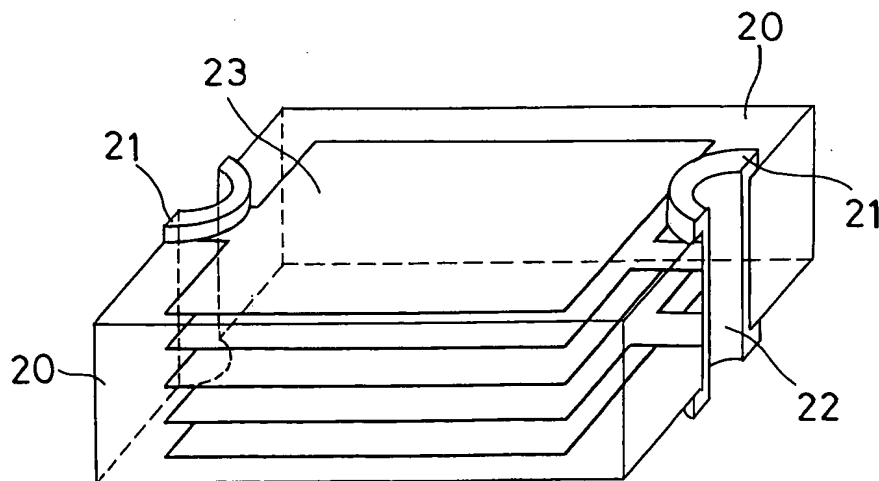
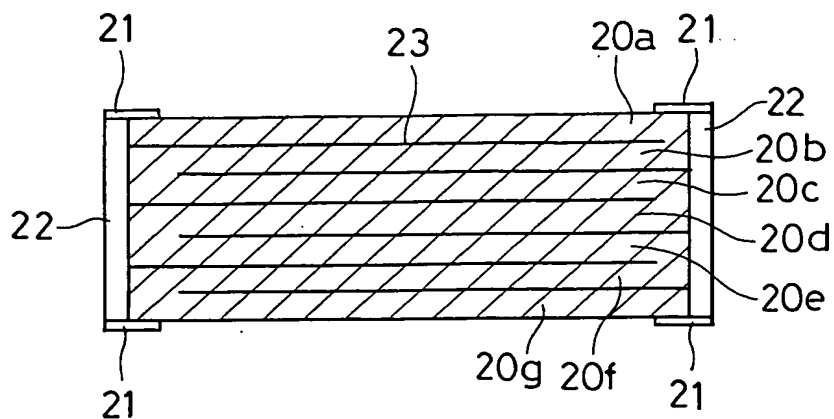


FIG. 22



00822T" 00864250

FIG. 23



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FIG. 24

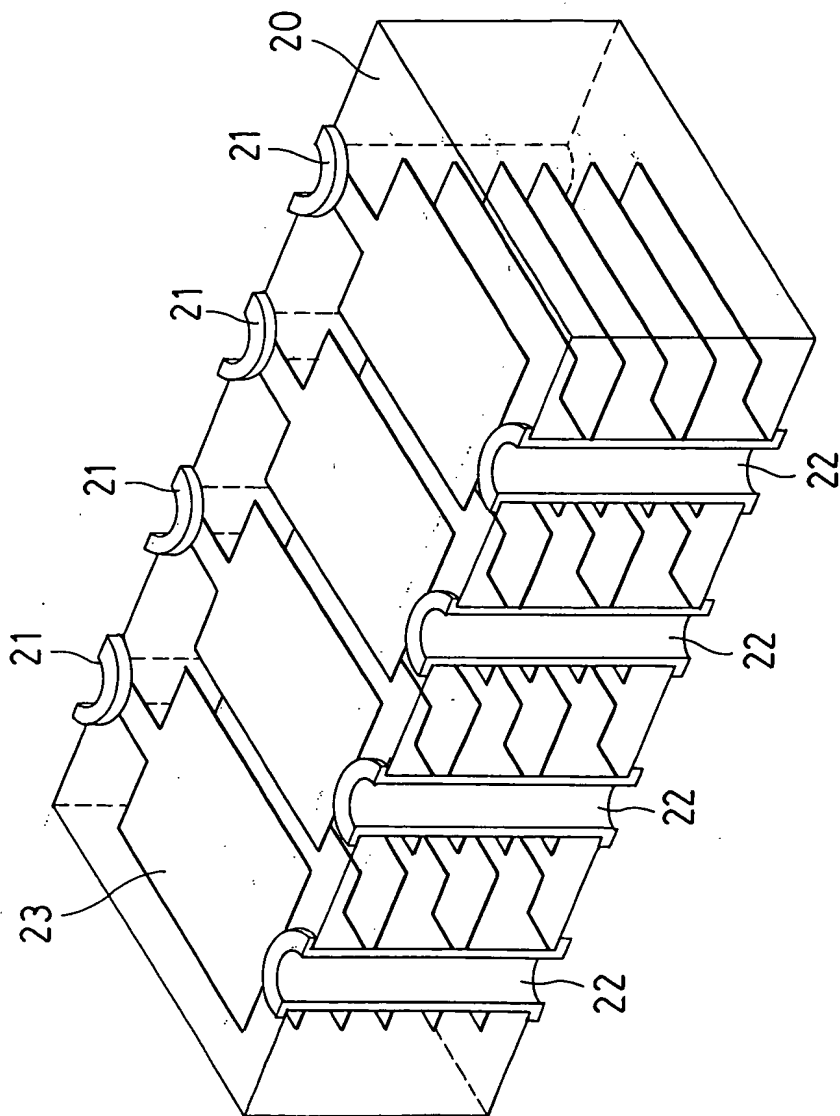


FIG. 25A

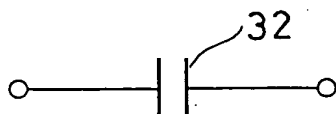


FIG. 25B

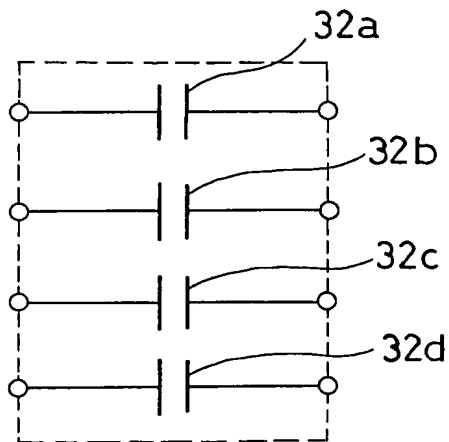
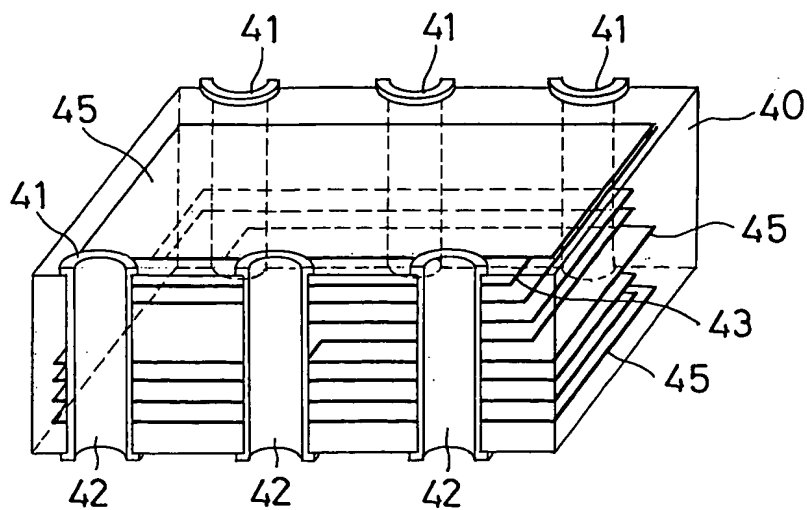


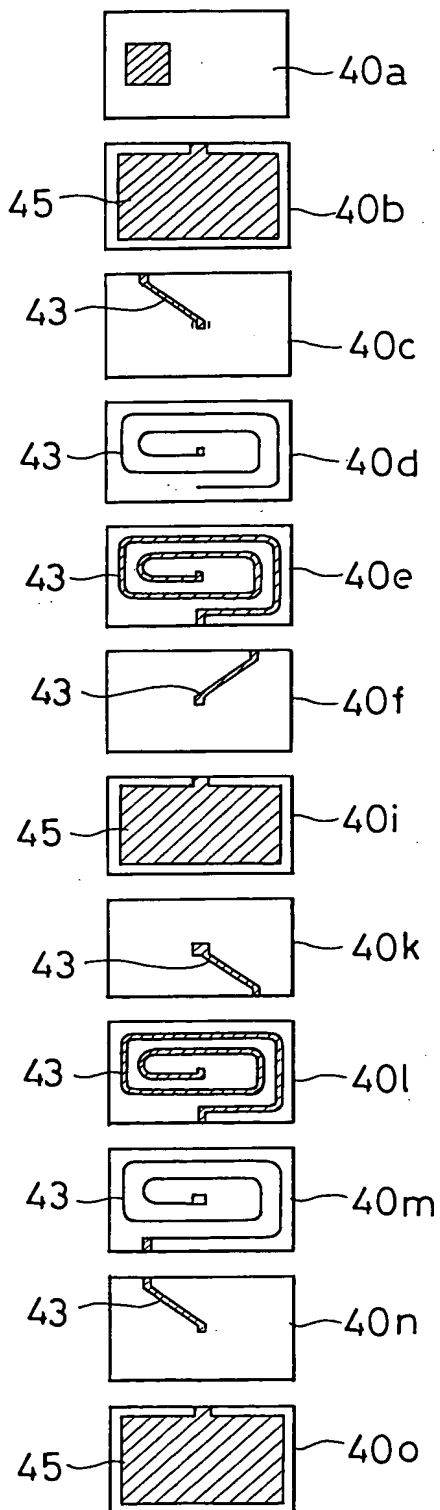
FIG. 26



008227" 00864/60

[illegible]

FIG. 28



008221" 00864260

FIG. 29

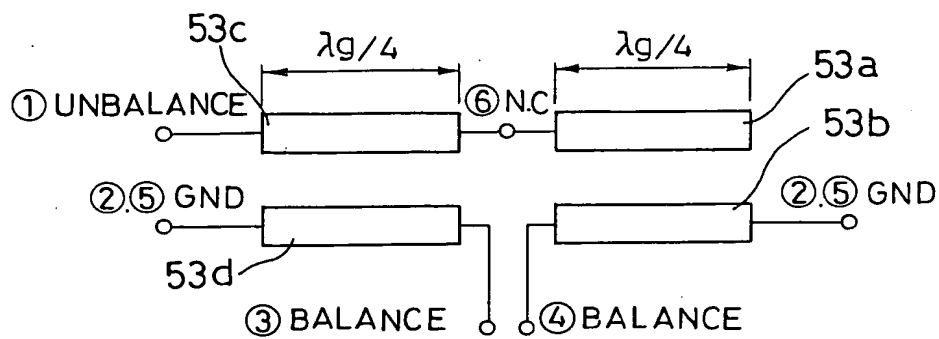
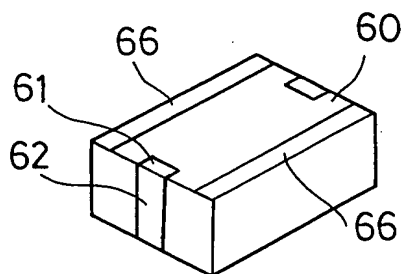
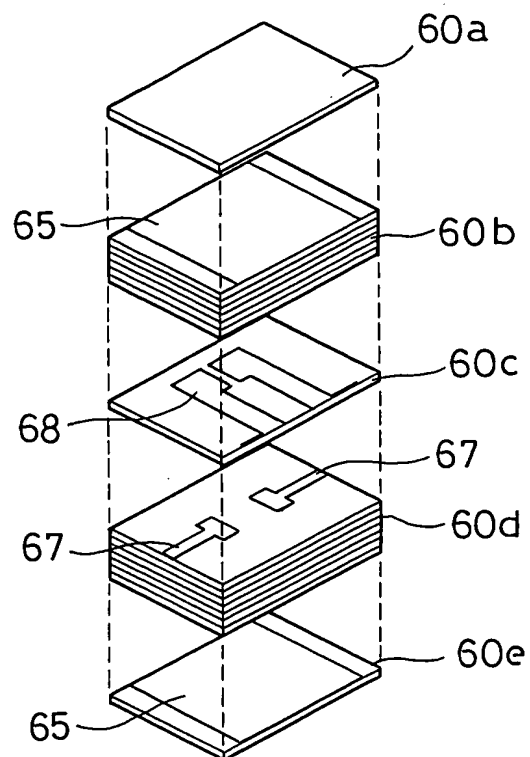


FIG. 30



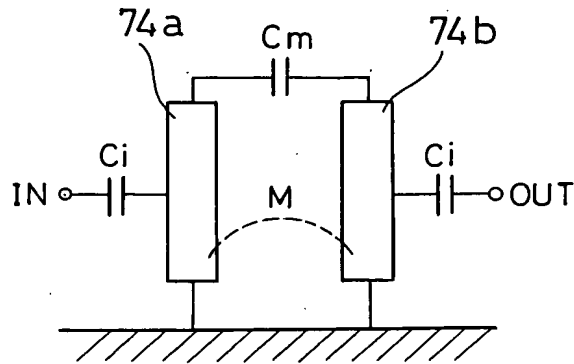
008221" 00864260

FIG. 31



09749800-122800

FIG. 32



008221 00364260

FIG. 33

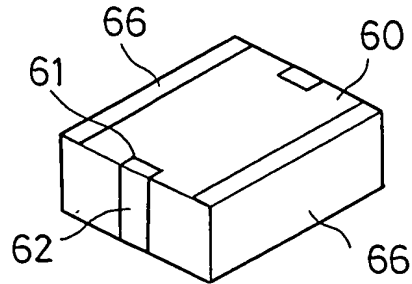
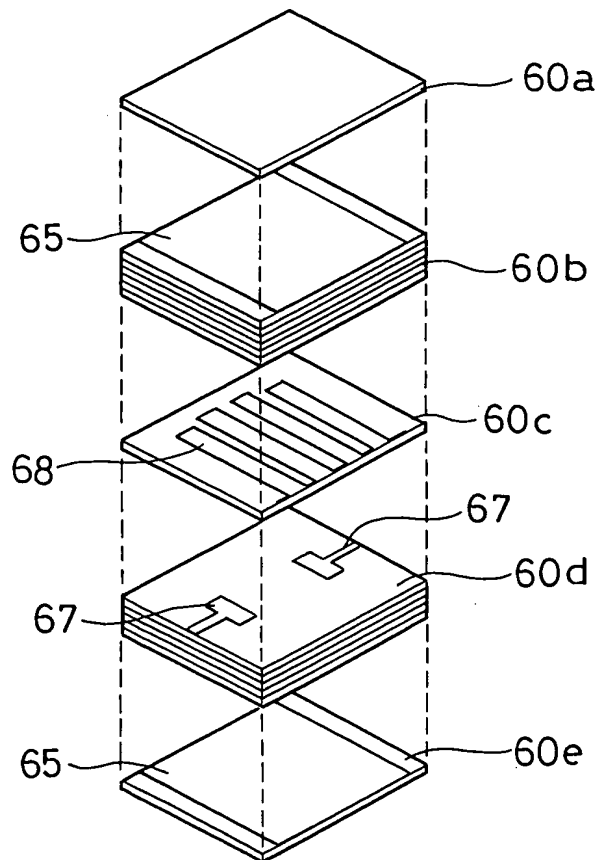
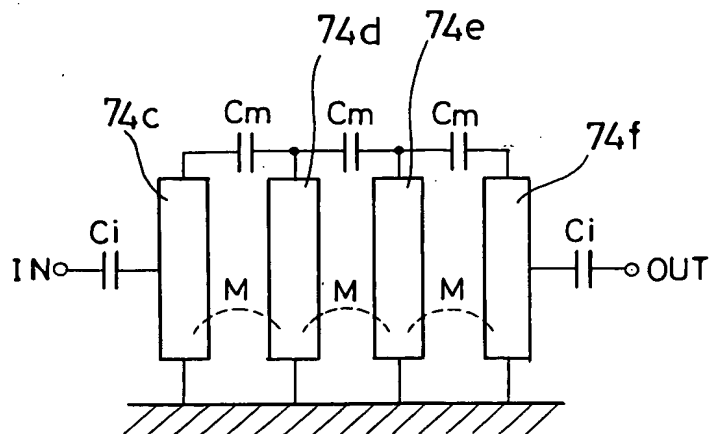


FIG. 34



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FIG. 35



09749800 122800

FIG. 36

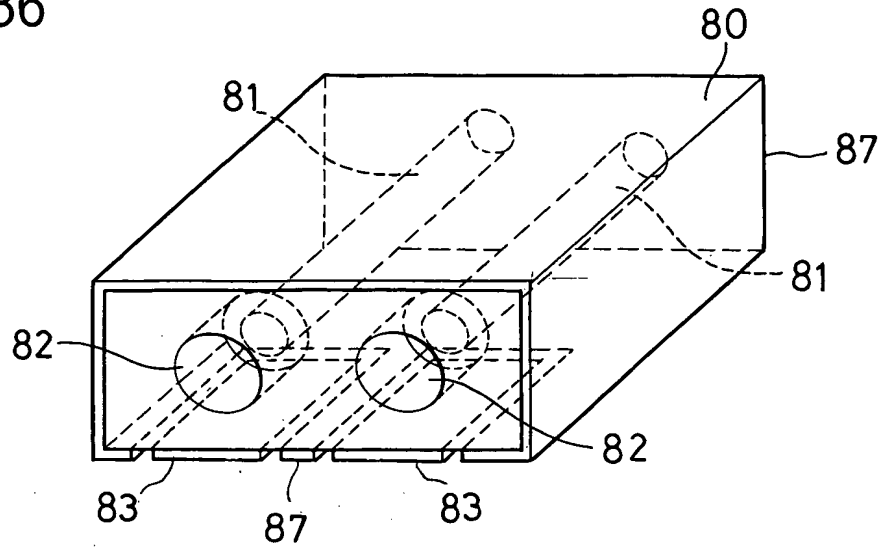


FIG. 37

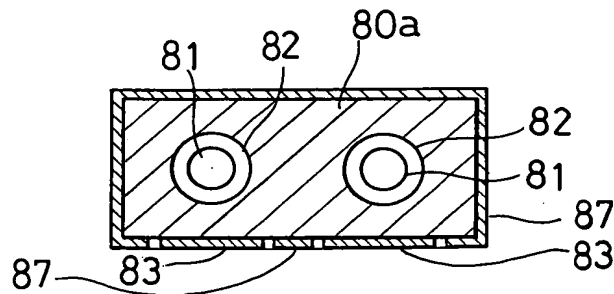


FIG. 38

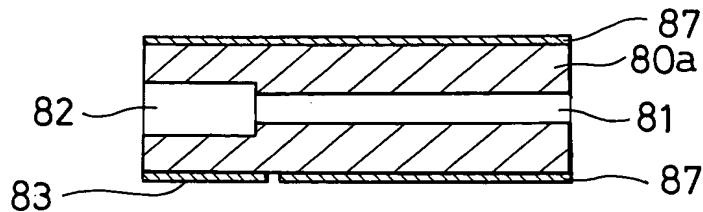
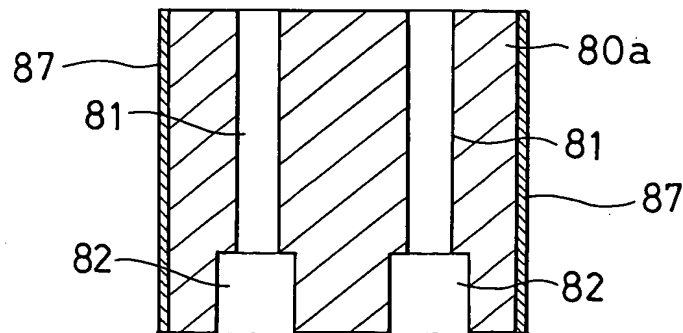


FIG. 39



008221" 00864260

FIG. 40

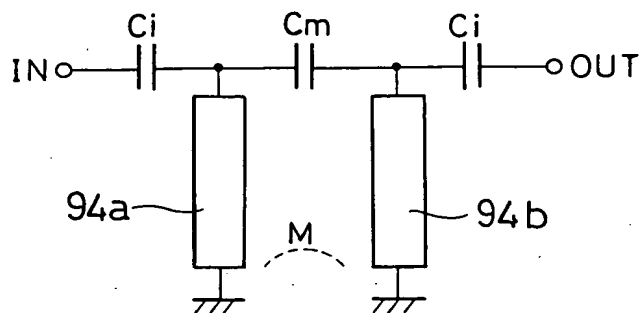
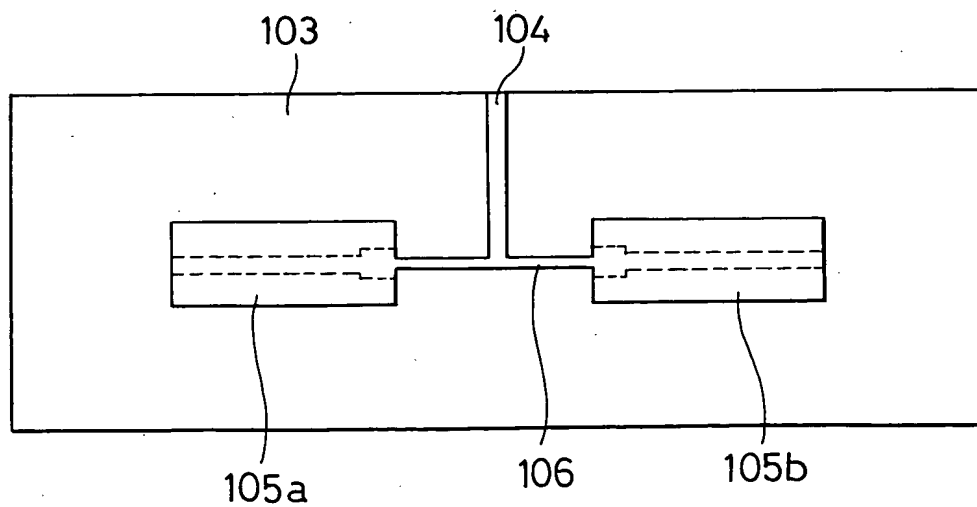


FIG. 41



00822T" 00854260

FIG. 42

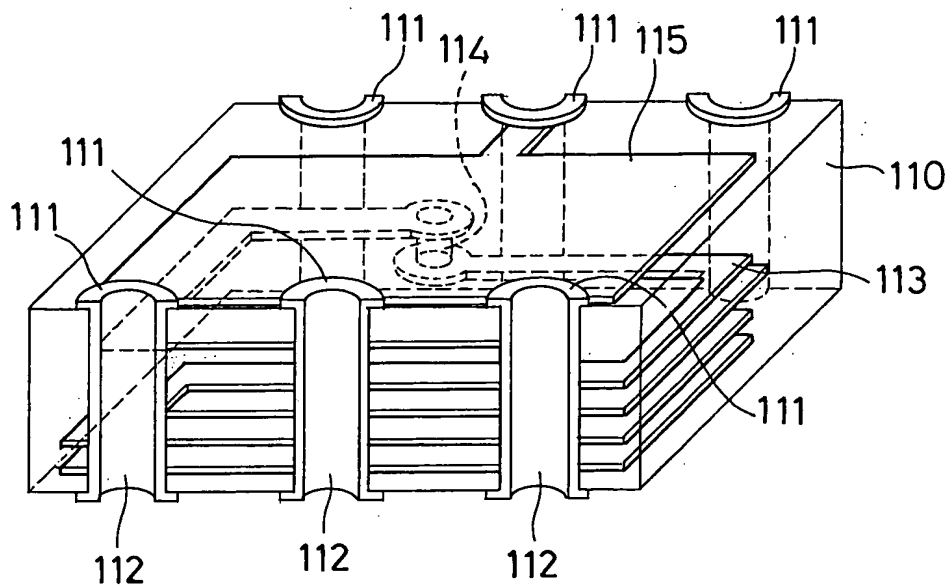


FIG. 43

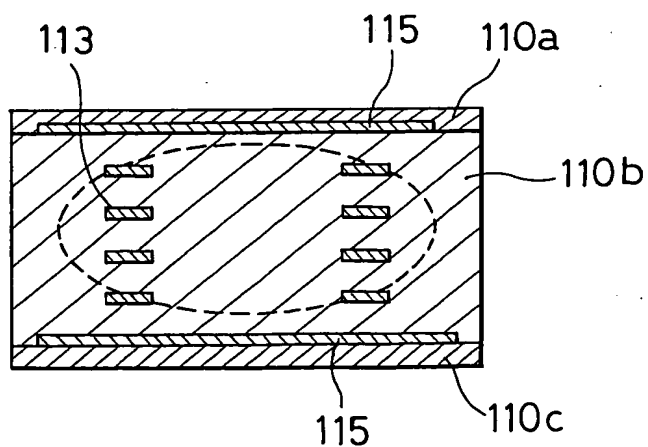
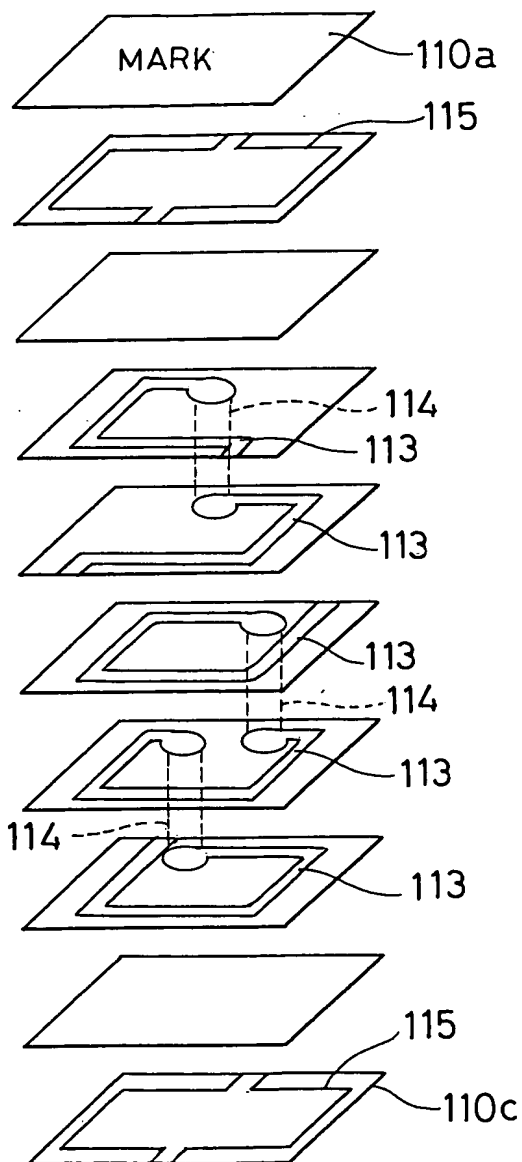


FIG. 44



008221" 00864260

A schematic diagram of a semiconductor device 110. The device is represented by a rectangular boundary. Inside, there are two coils, labeled 125a and 125b, arranged vertically. Each coil is connected to a central circuit block. This block contains a ground symbol (a triangle with diagonal lines) and is connected to a terminal 112 on the right side. There are six terminals labeled 112 in total: three on the top edge and three on the bottom edge. The top terminals are connected to the top of coils 125a and 125b, and the bottom terminals are connected to the bottom of these coils. The central circuit block is connected to the rightmost terminal on both the top and bottom edges.

FIG. 47

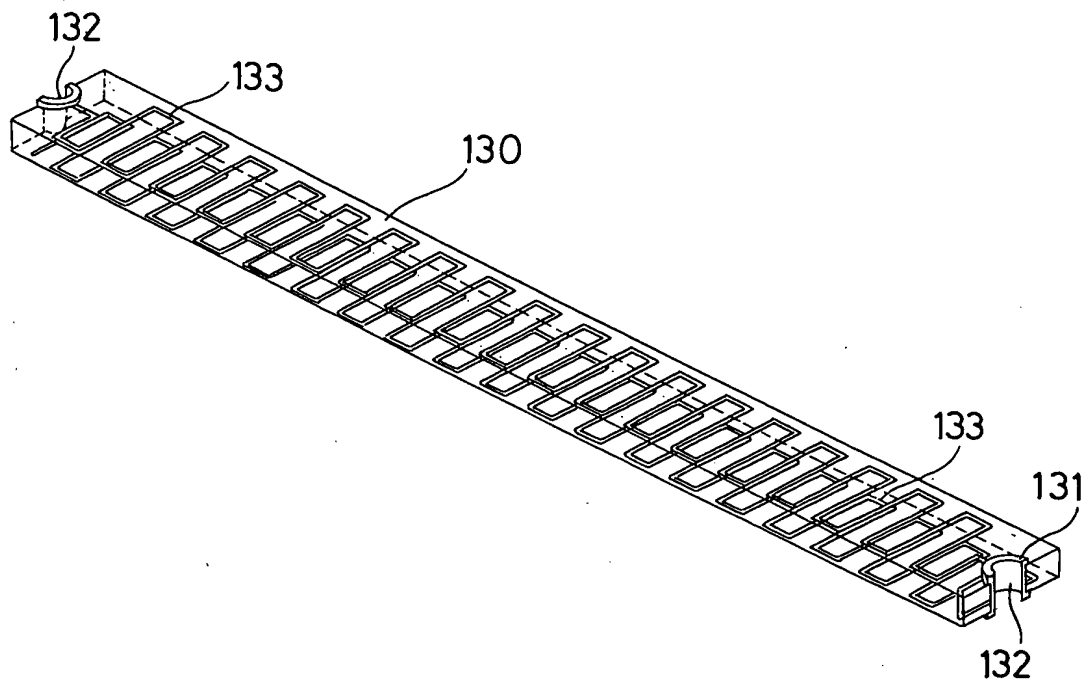


FIG. 48A

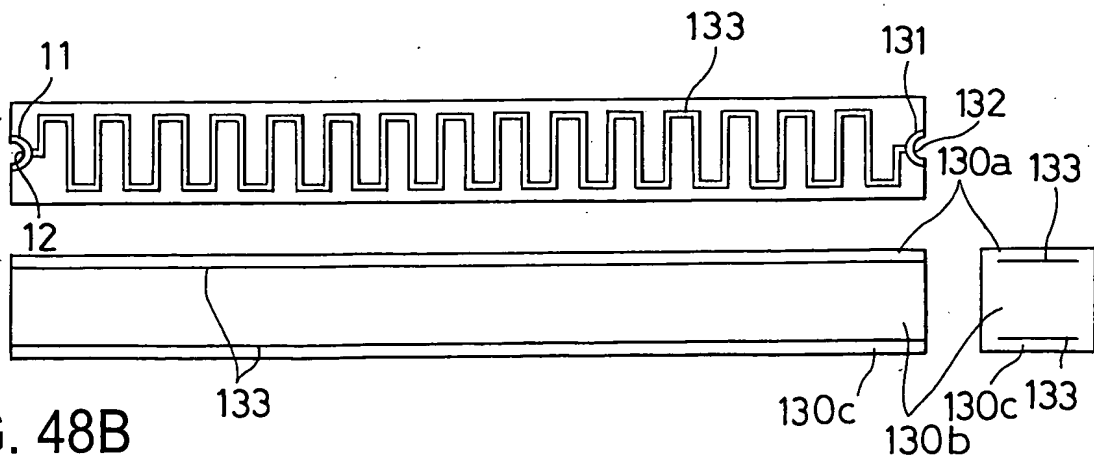
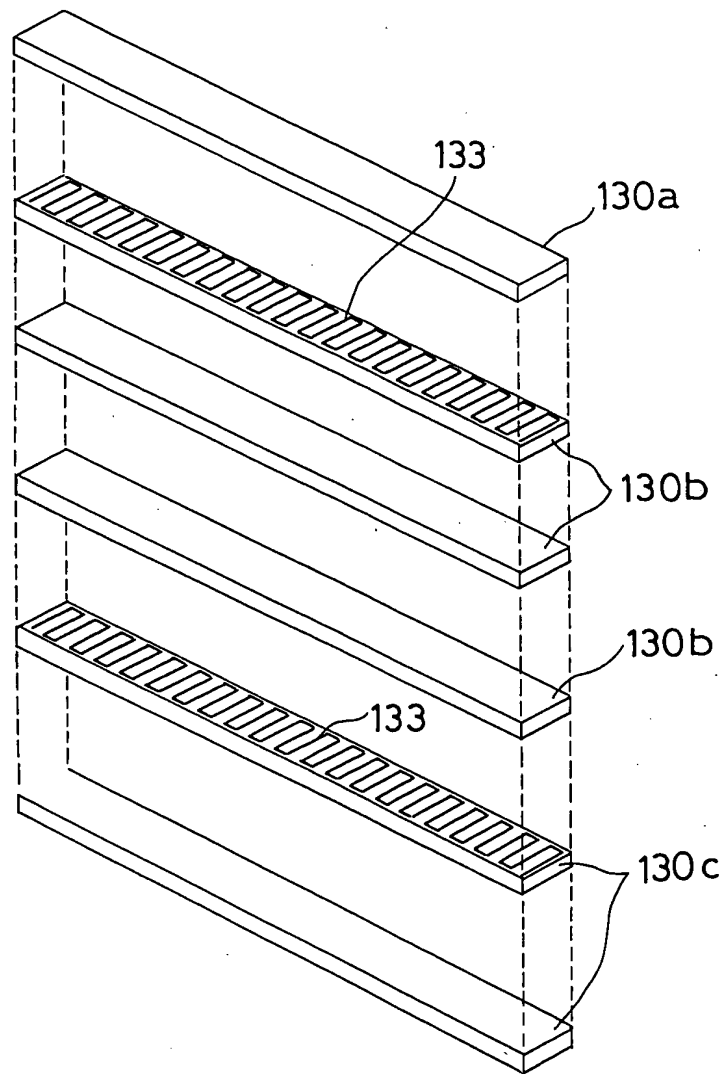


FIG. 48B

FIG. 48C

00822T 00864260

FIG. 49



008221 0086460

FIG. 50

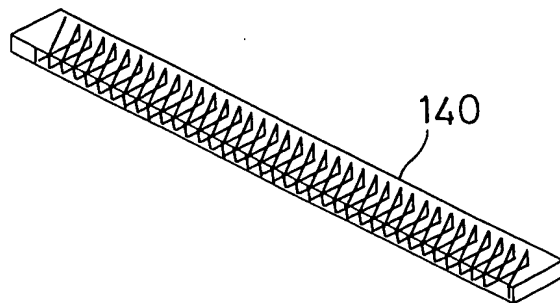
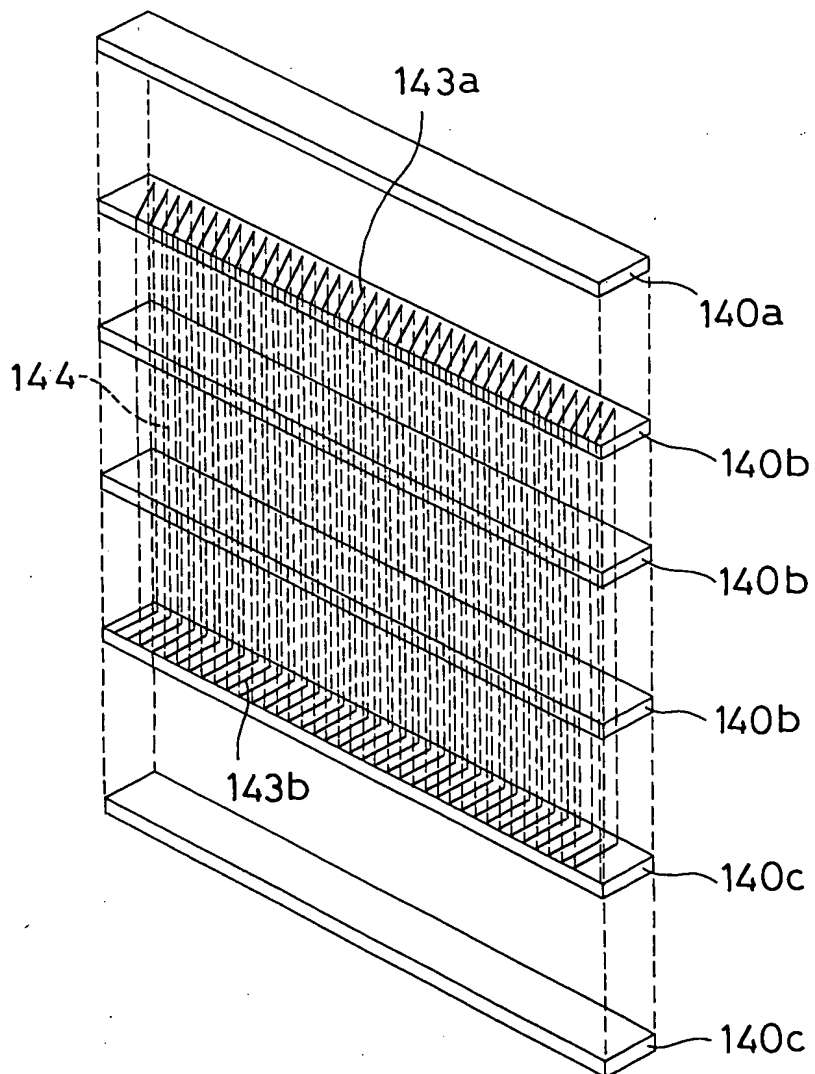


FIG. 51



008221 00854750

FIG. 52

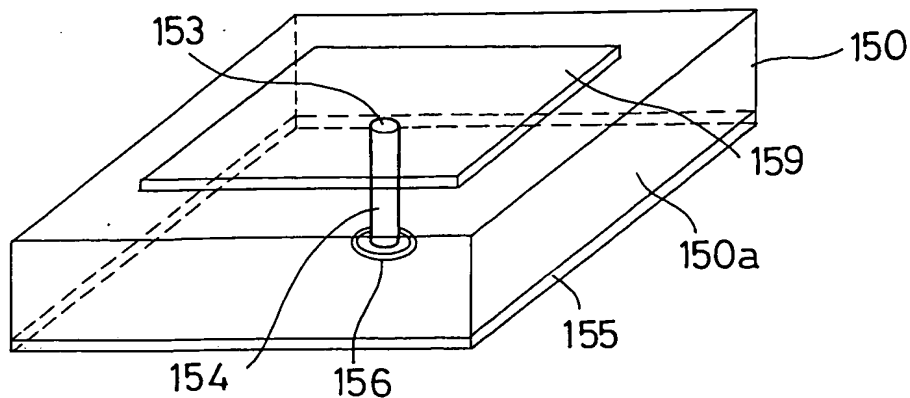


FIG. 53

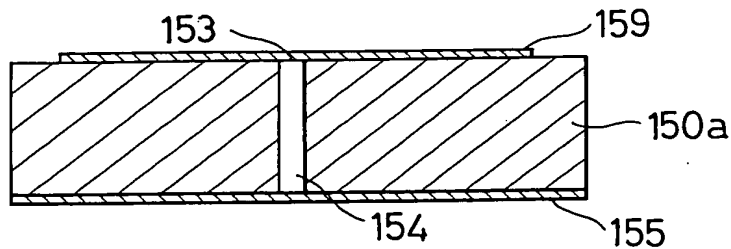


FIG. 54

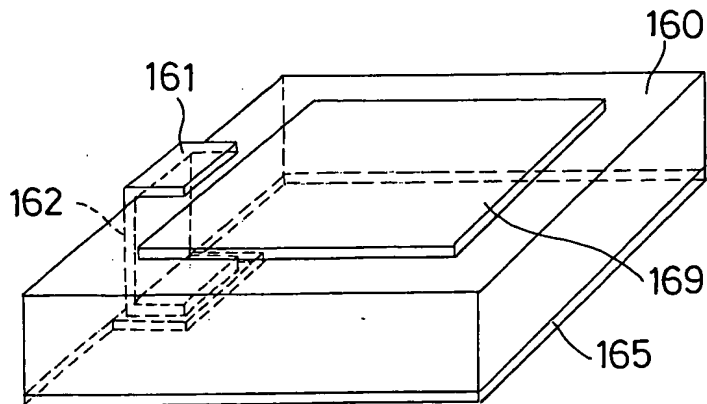


FIG. 55

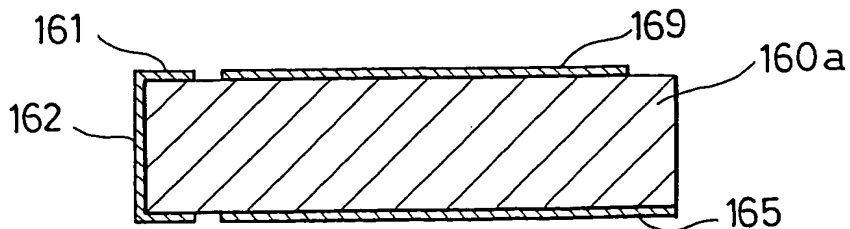


FIG. 56

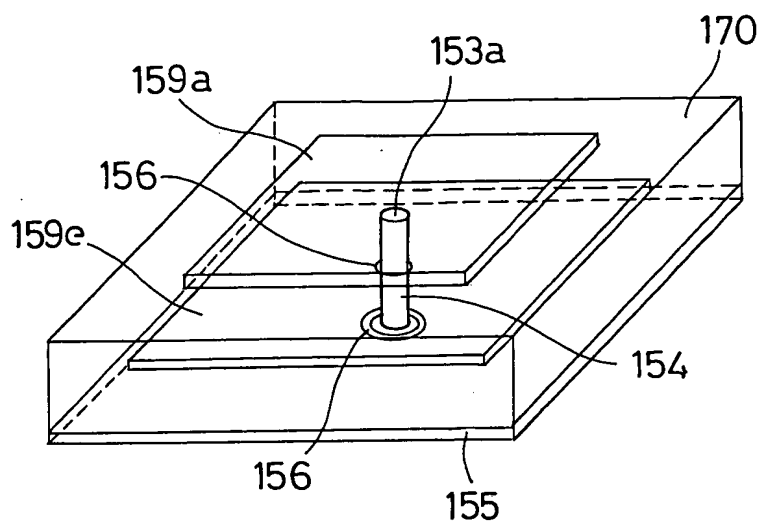


FIG. 57

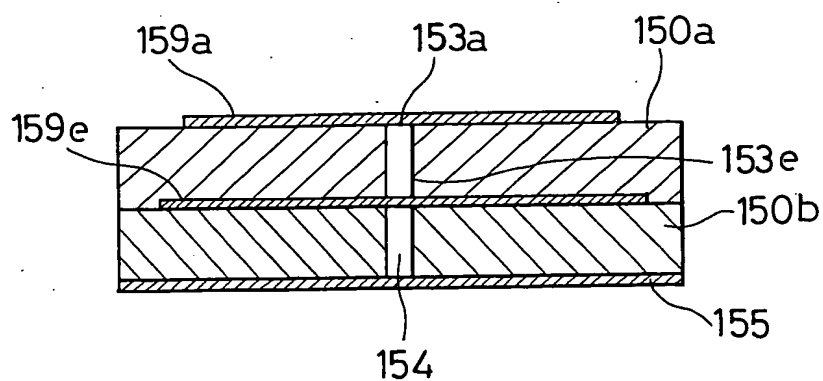


FIG. 58

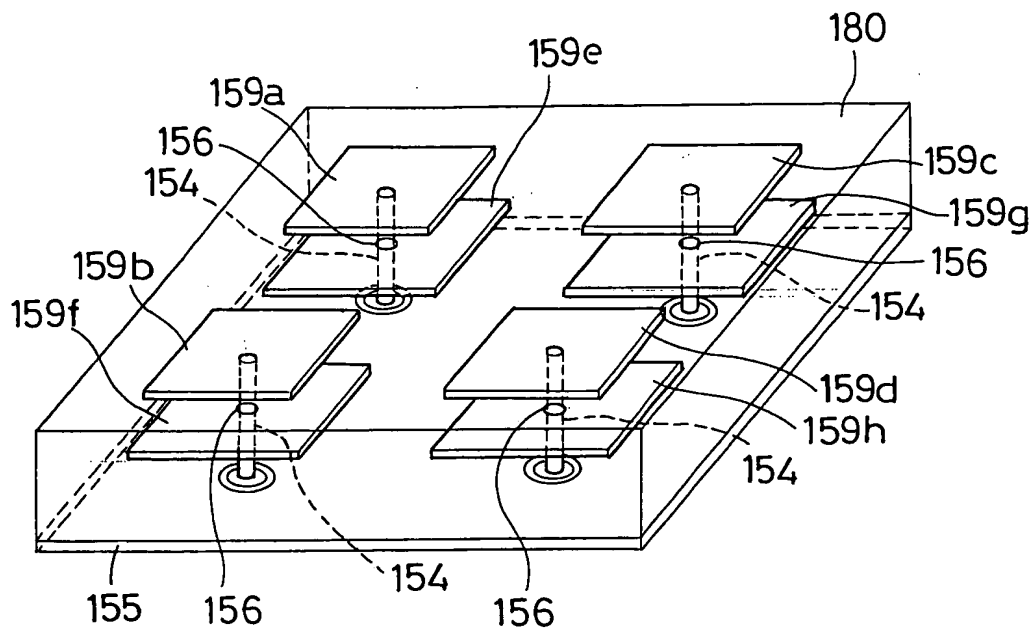


FIG. 59

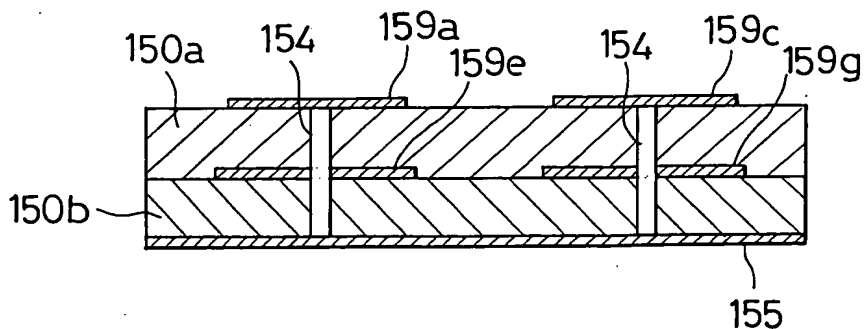


FIG. 60

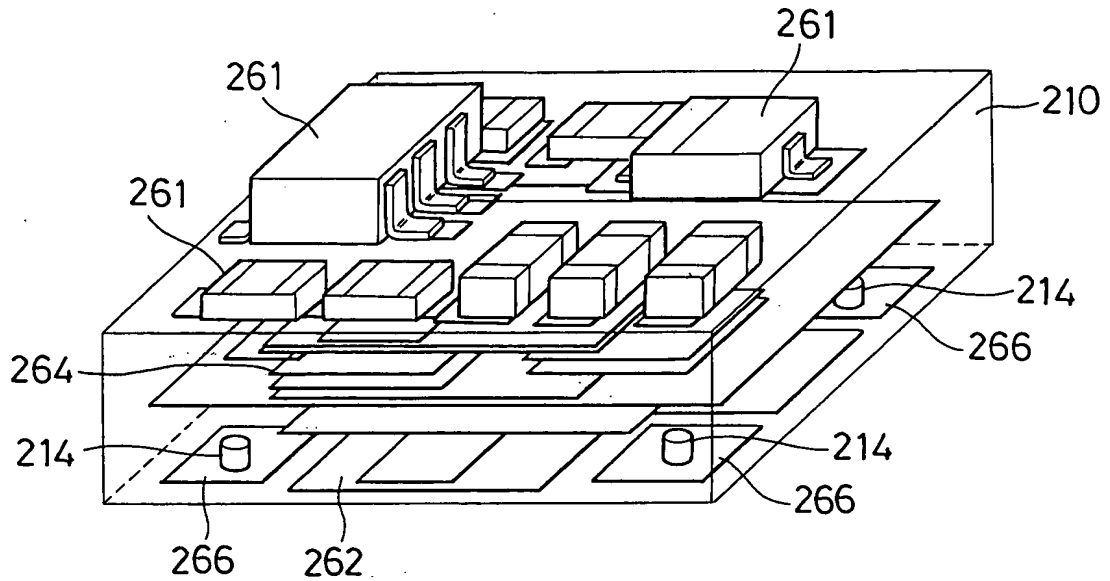


FIG. 61

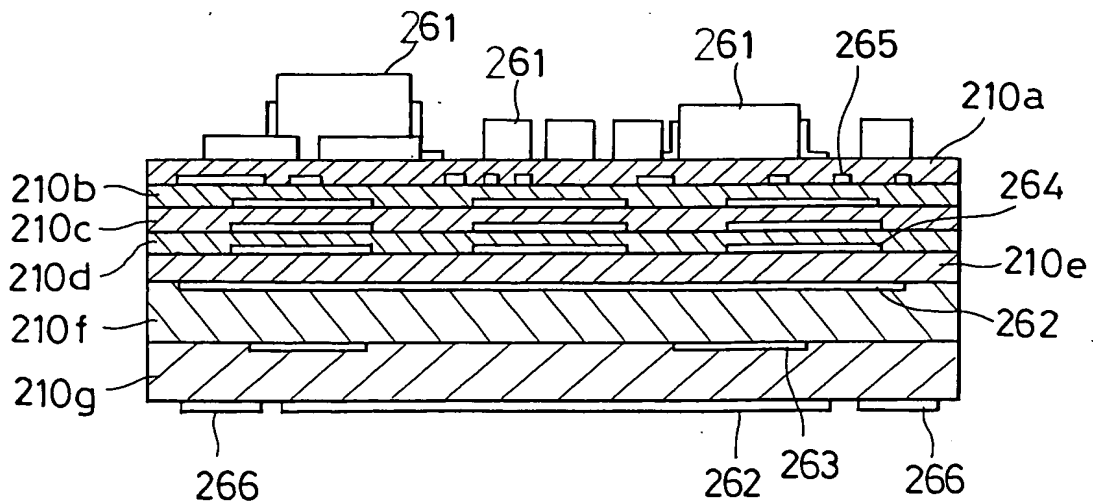
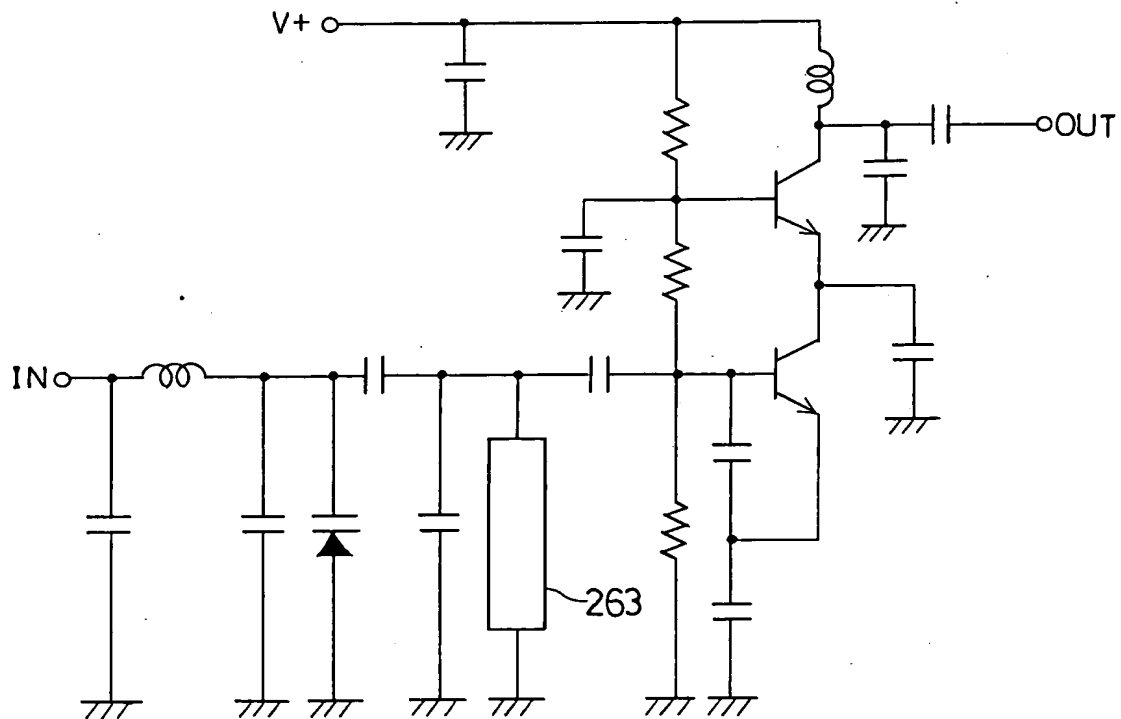
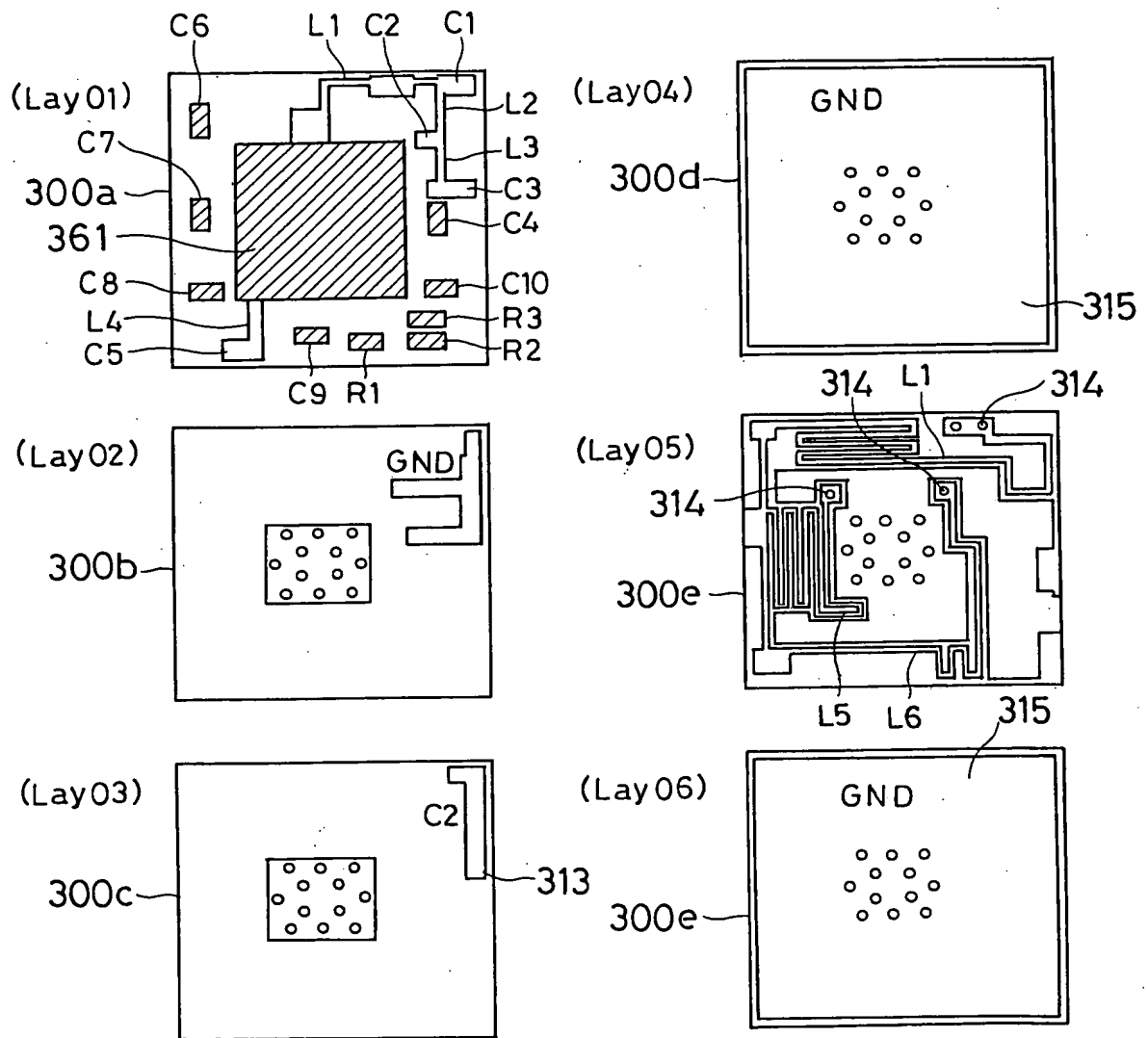


FIG. 62



003221" 00864260

FIG. 63



008221" 00864260

FIG. 64

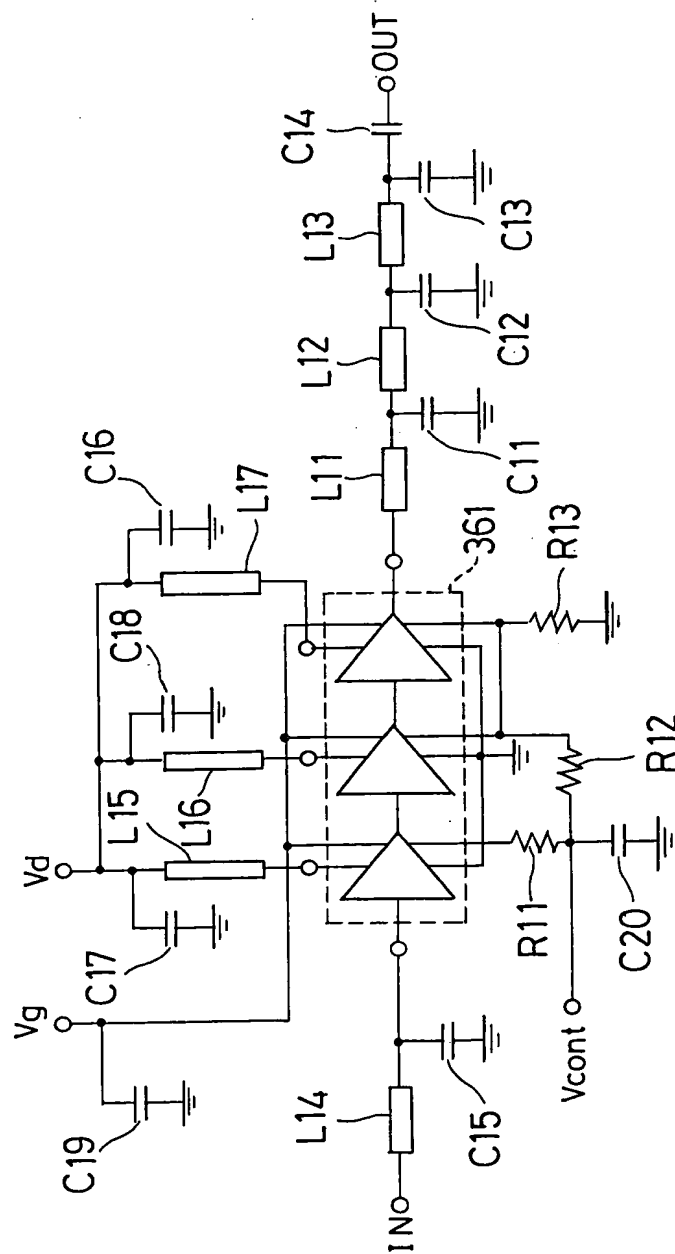


FIG. 65

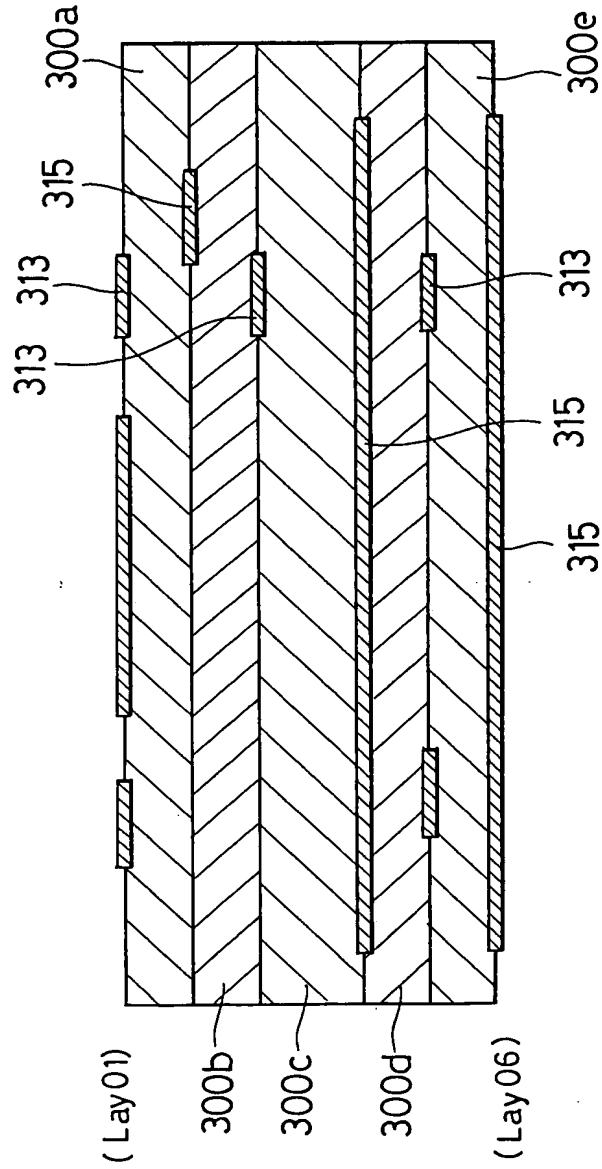
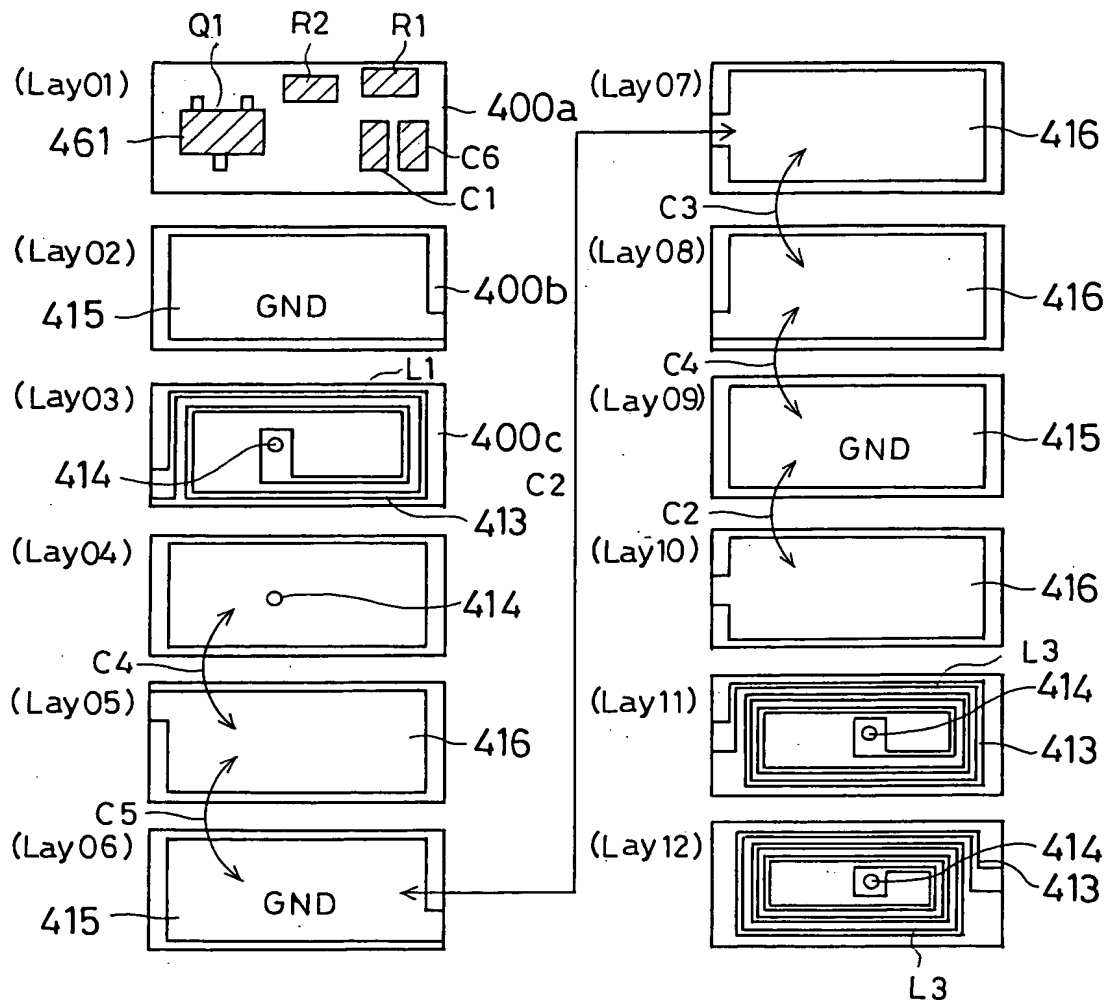


FIG. 66



003221" 00864260

FIG. 67

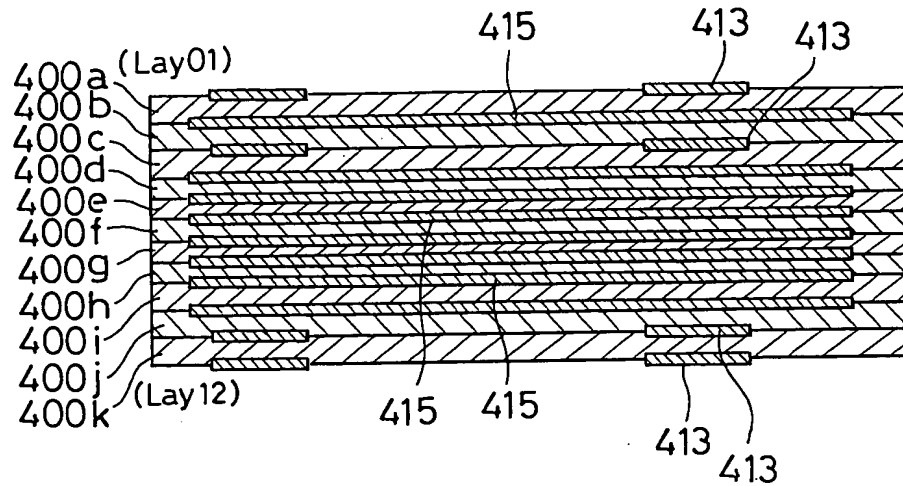
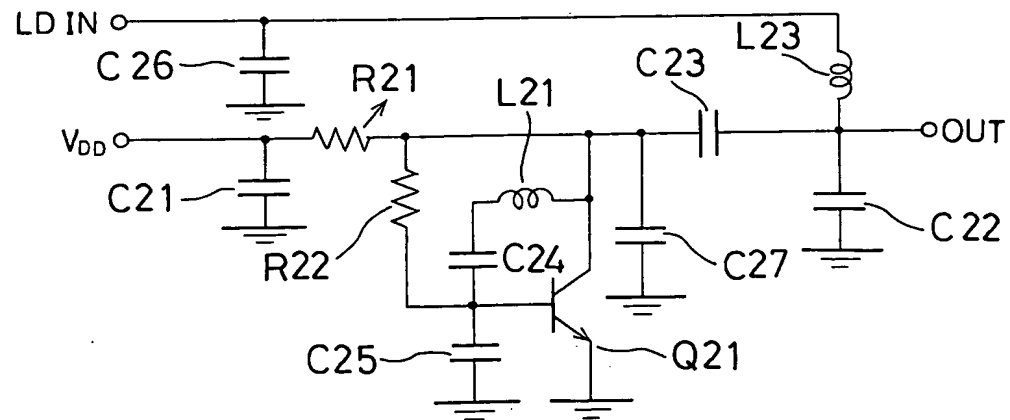
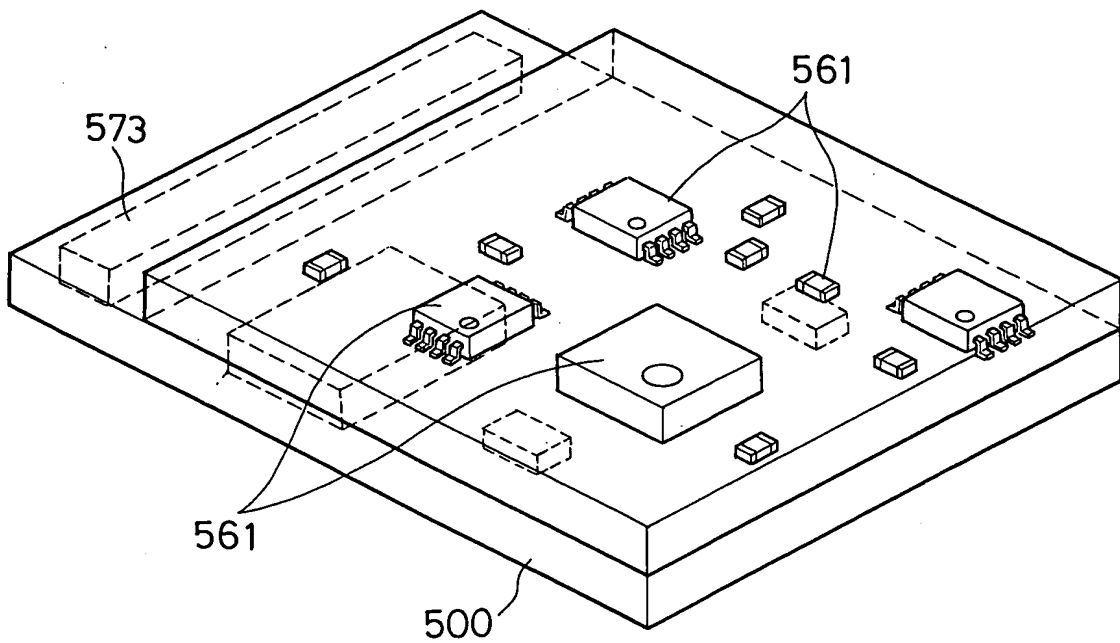


FIG. 68



00822T"00864260

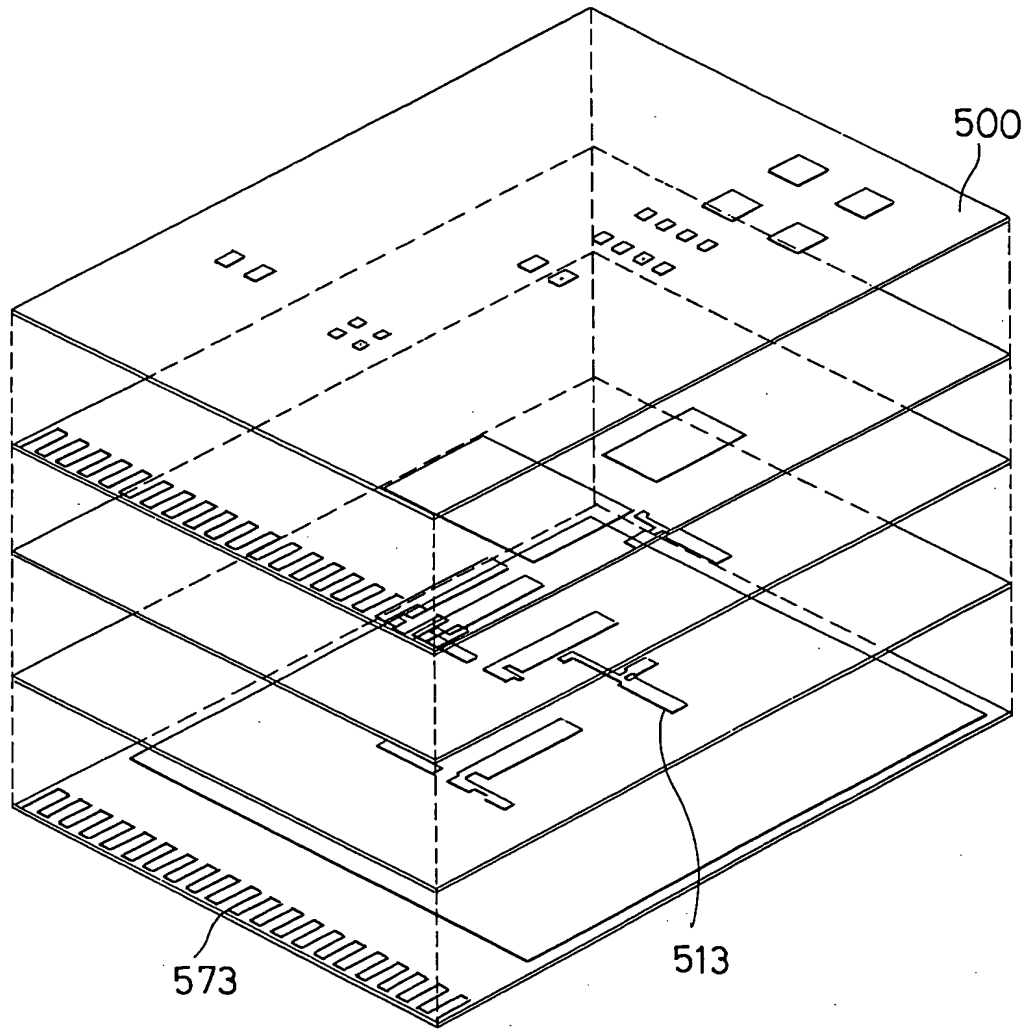
FIG. 69



008221" 00864260

Figure 5 is a perspective view of a circuit board 500. The board features a series of parallel conductive strips 573 along one edge. Various electronic components, including integrated circuits and resistors, are mounted on the surface. Two specific components are labeled 561.

FIG. 71



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FIG. 72

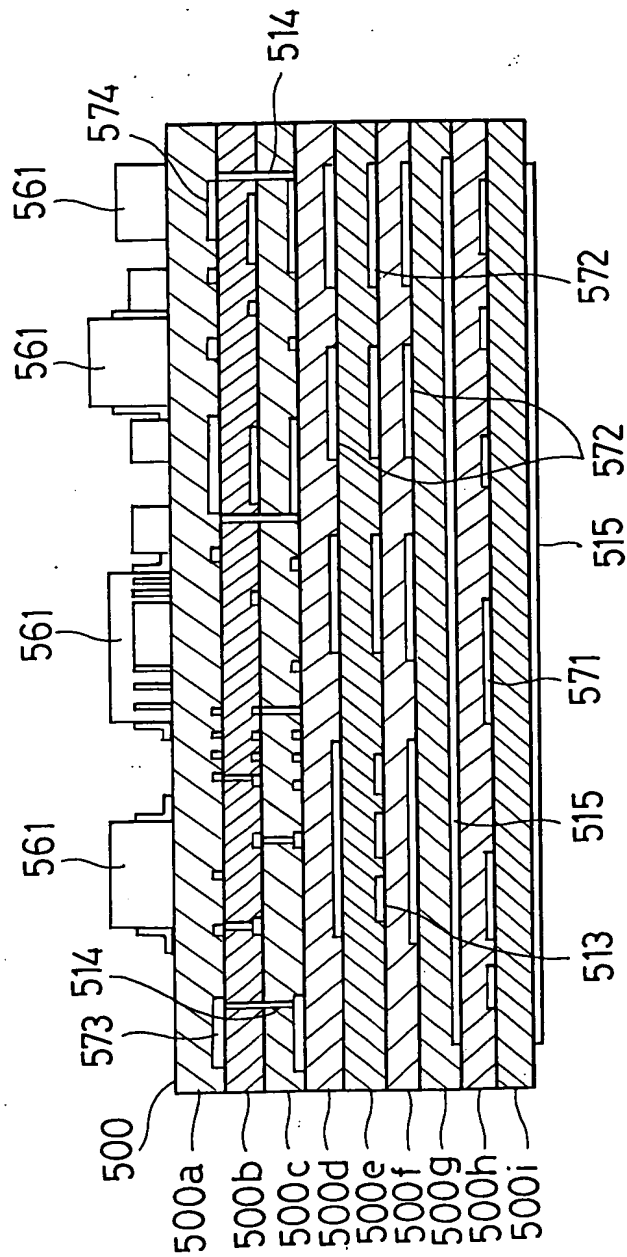


FIG. 73

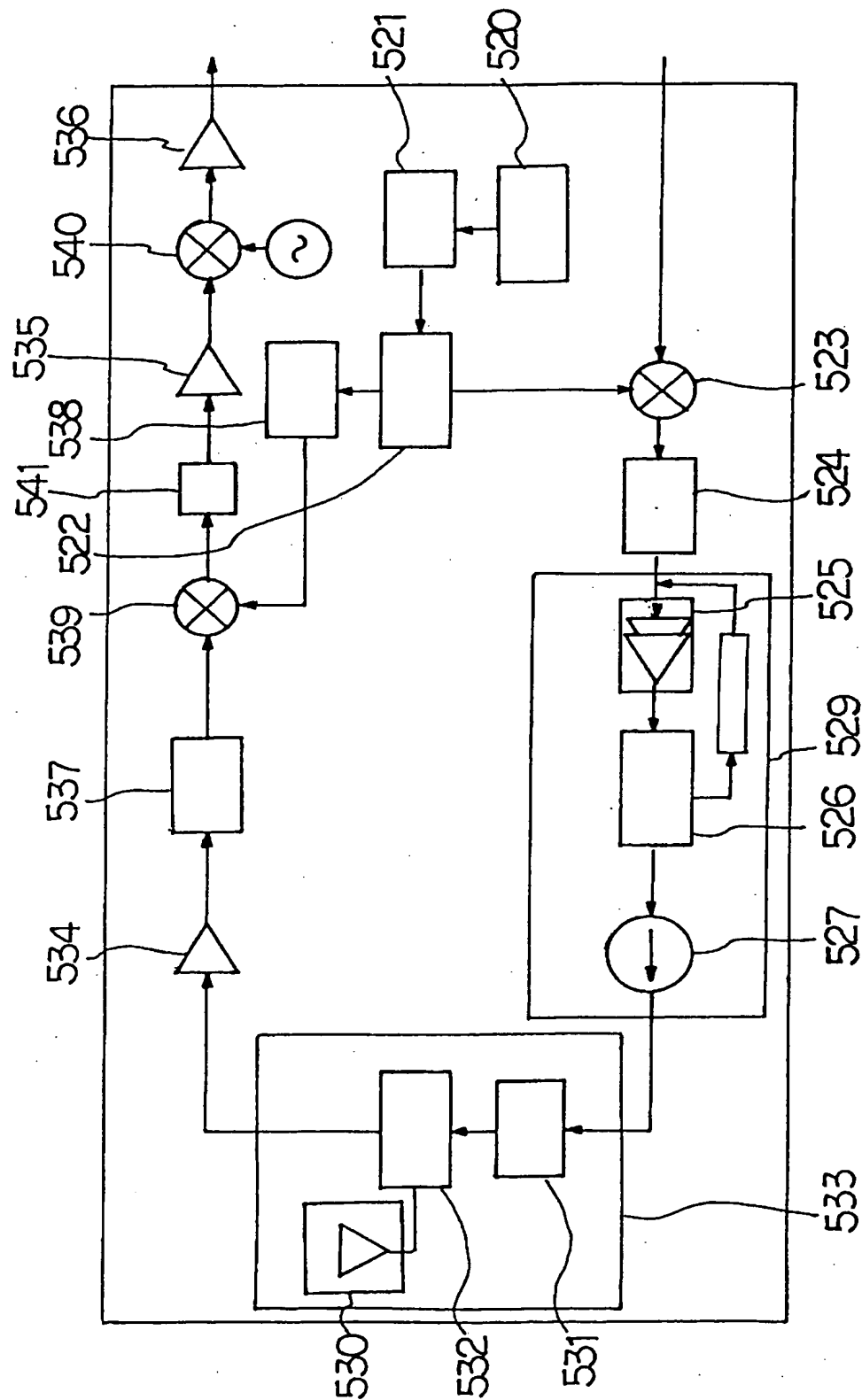


FIG. 74

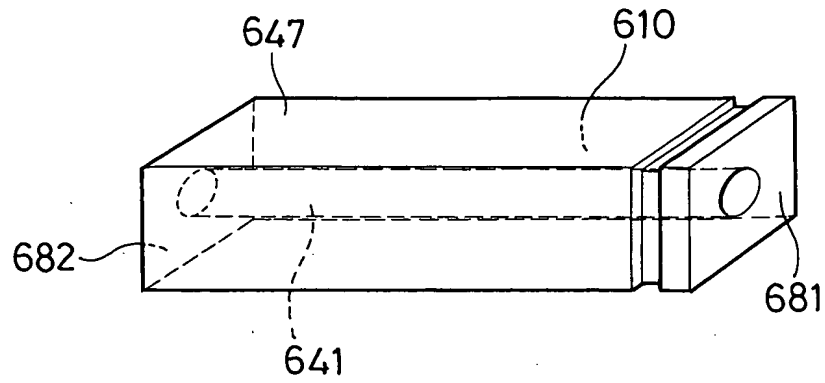


FIG. 75

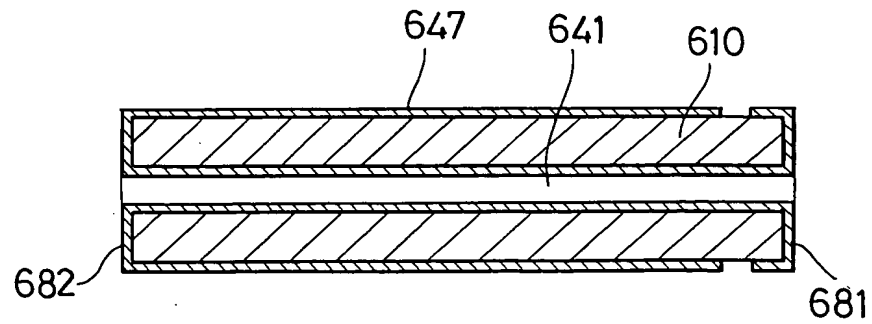


FIG. 76

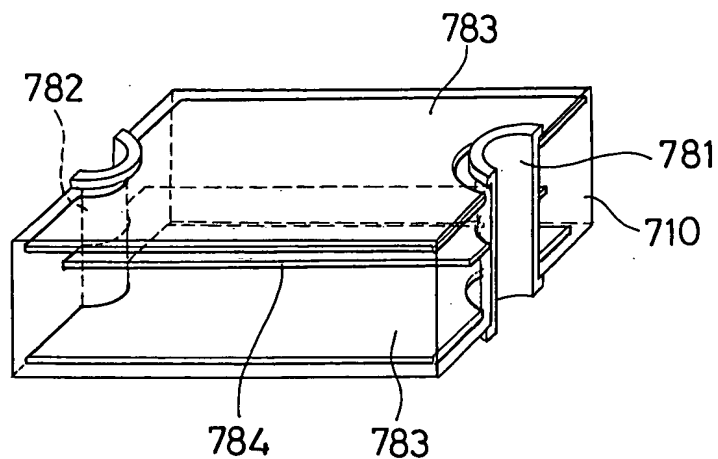
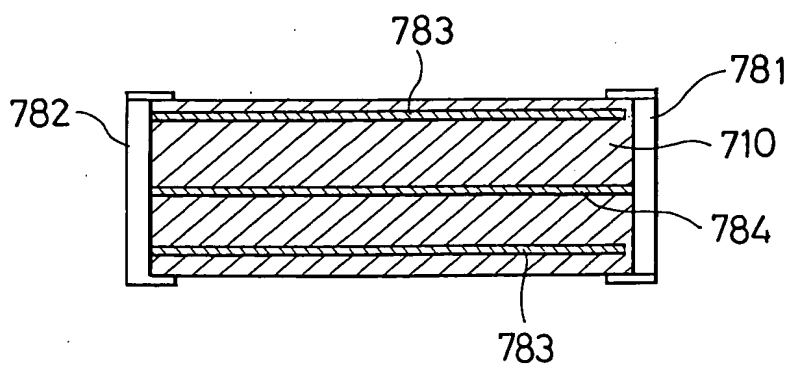


FIG. 77



00822T" 00864260

FIG. 79

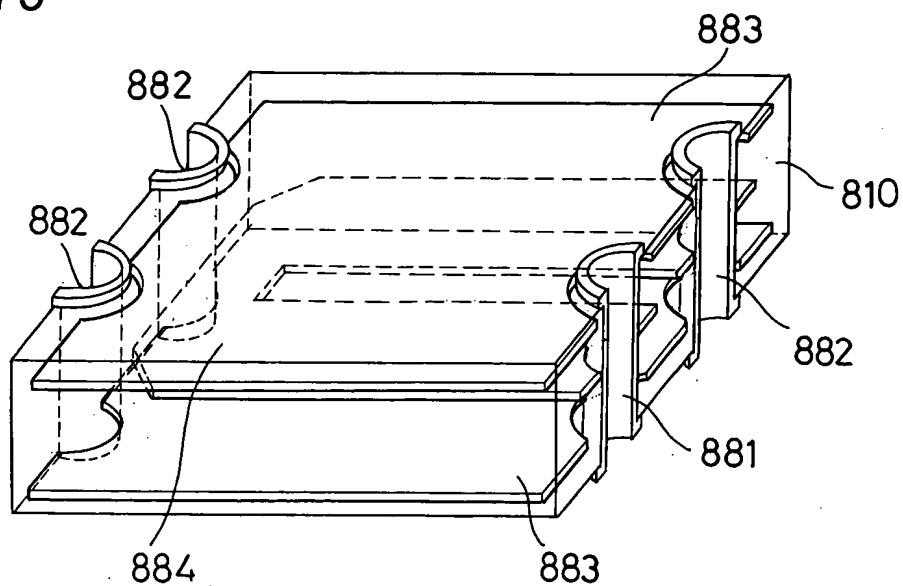


FIG. 80

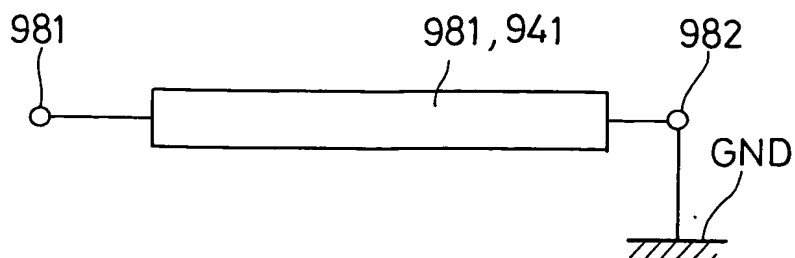


FIG. 81A

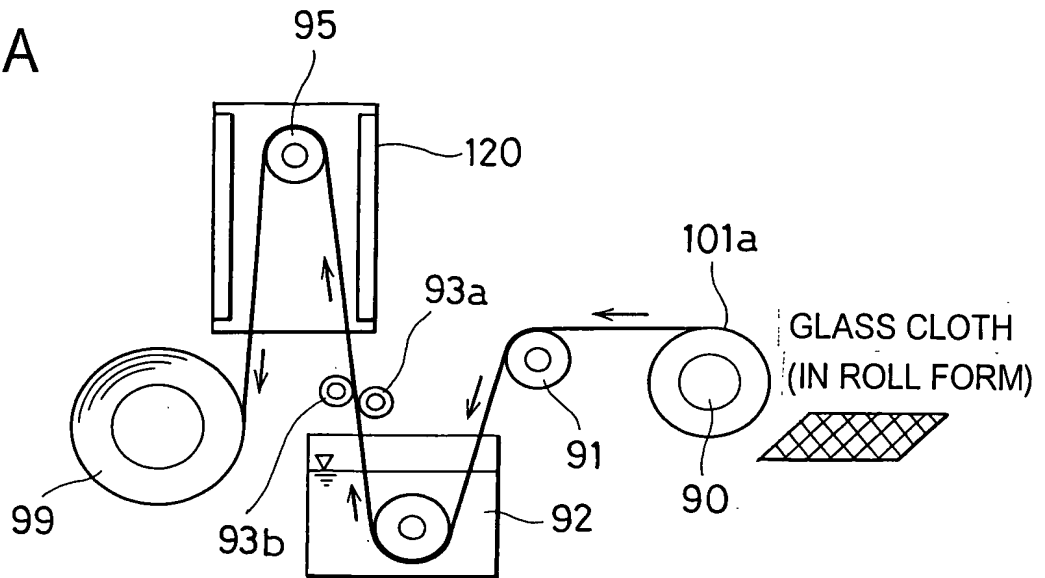


FIG. 81B

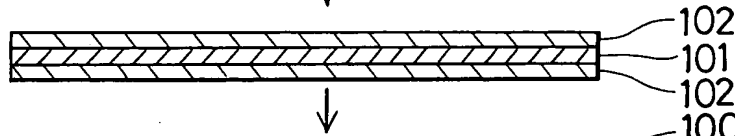


FIG. 81C

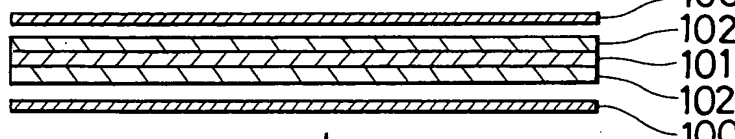
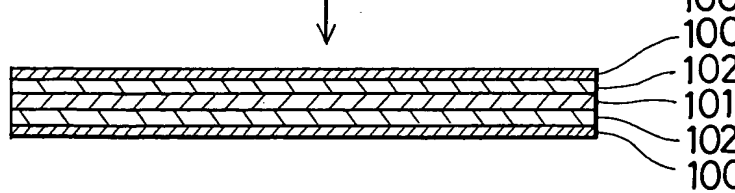


FIG. 81D



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FIG. 82A

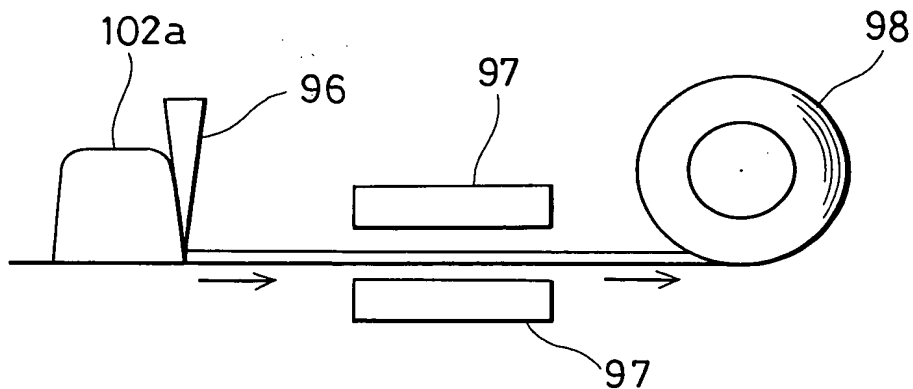


FIG. 82B

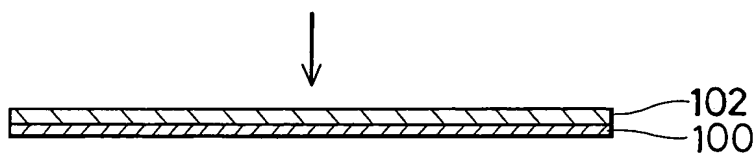


FIG. 82C

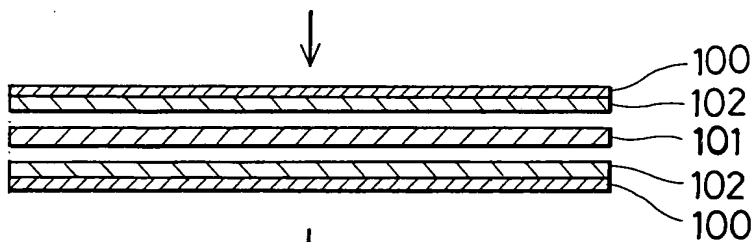
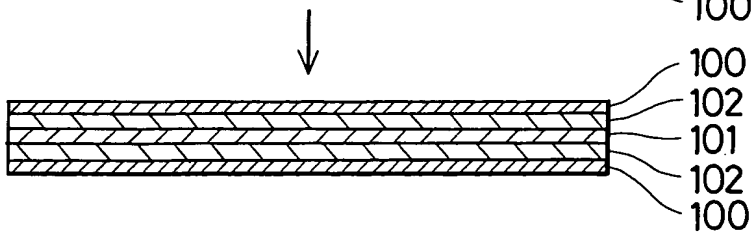
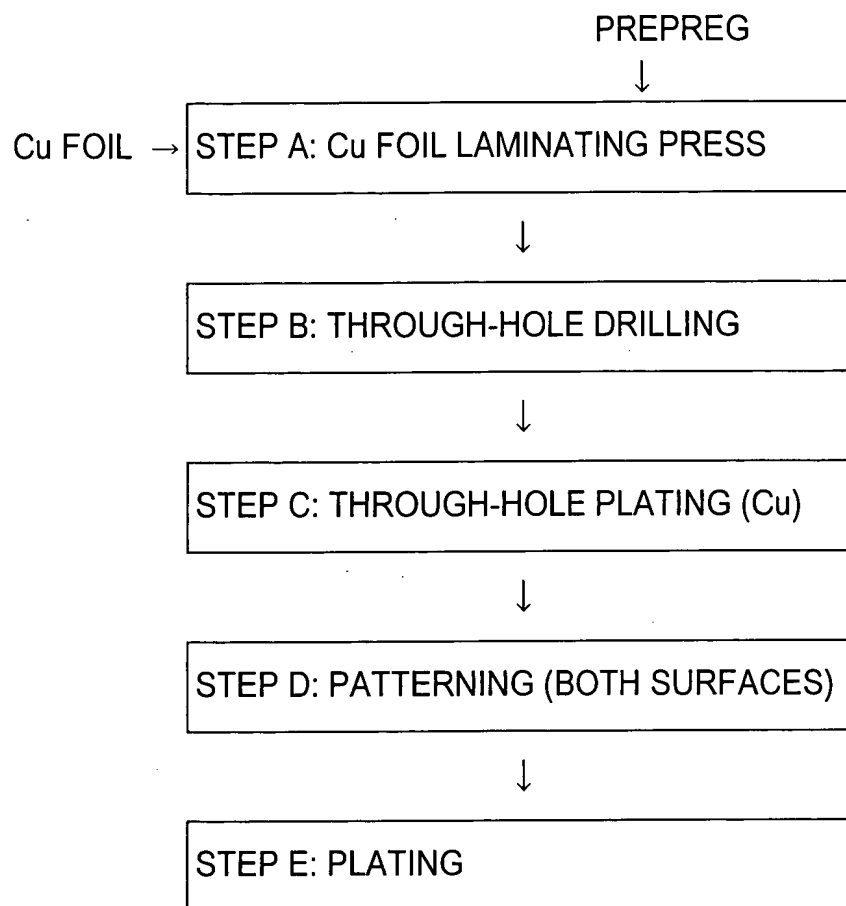


FIG. 82D



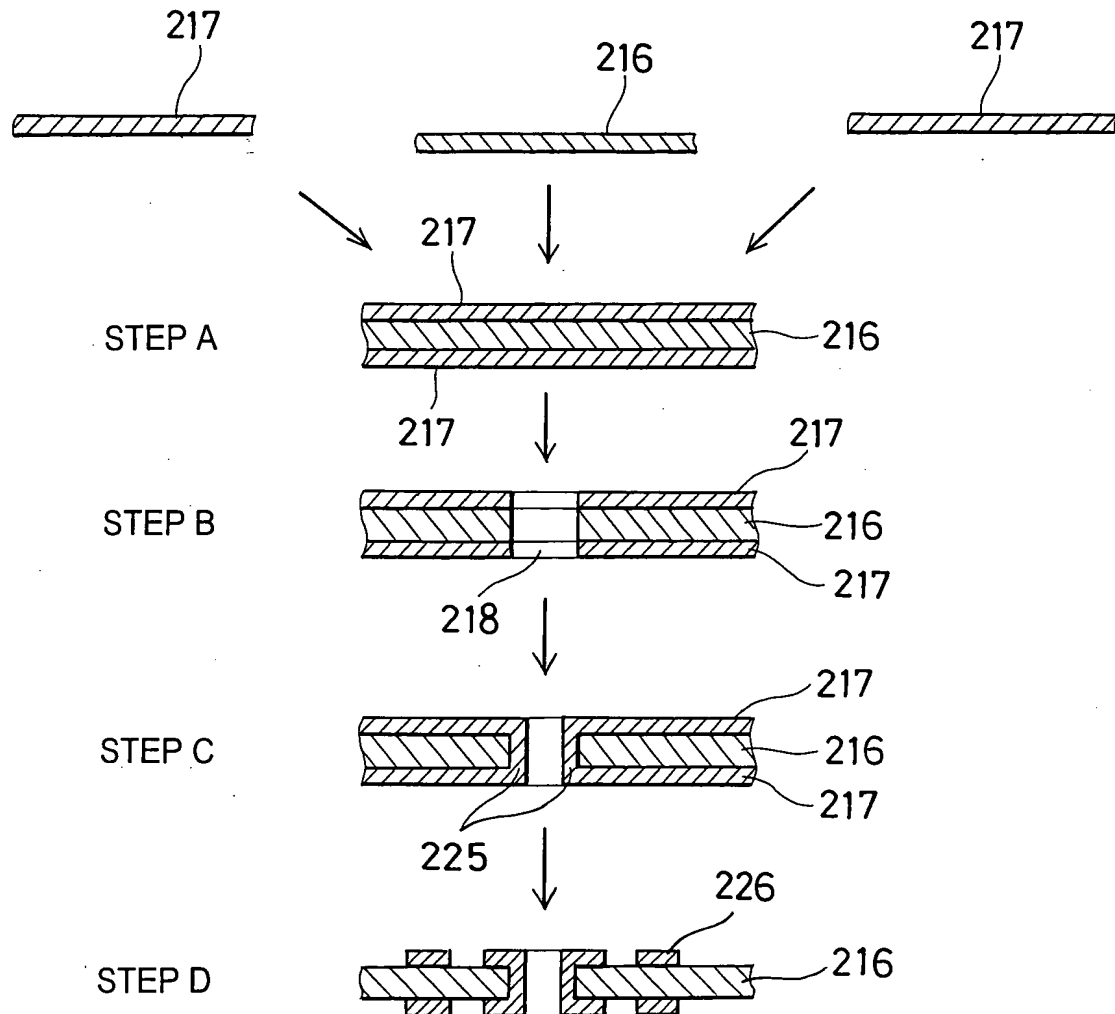
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FIG. 83



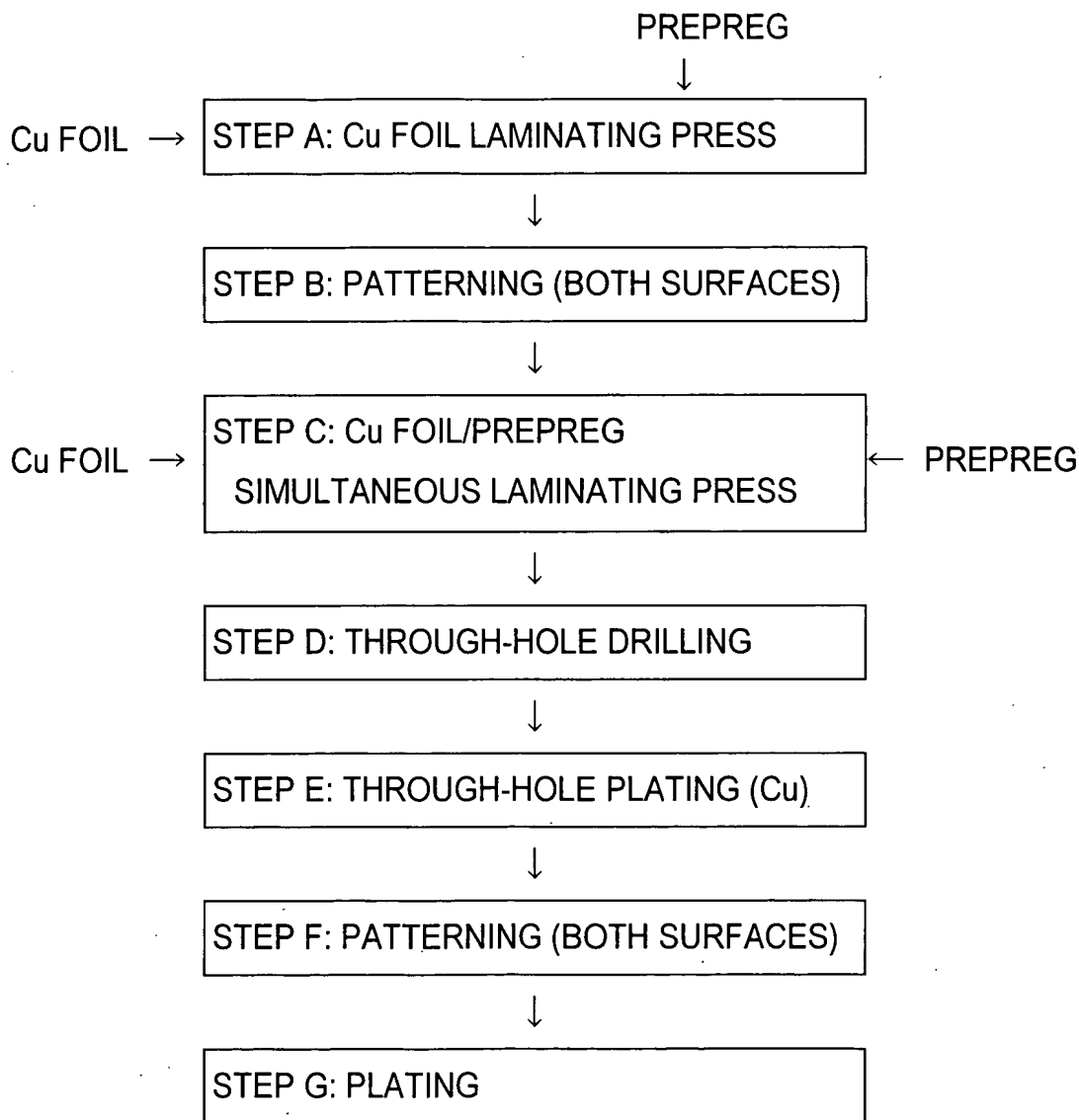
008221 0086460

FIG. 84



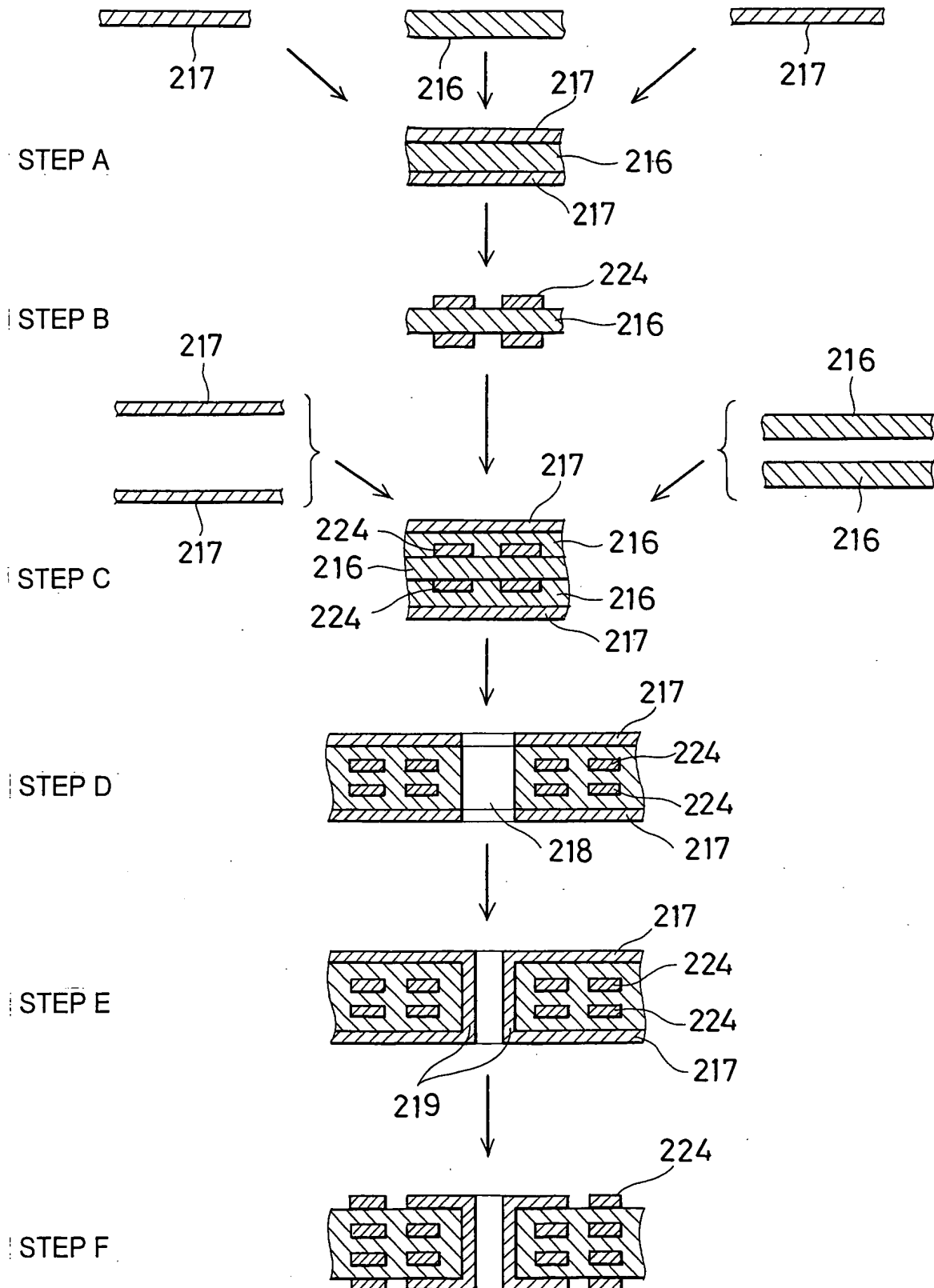
008227 00864260

FIG. 85



008221 0086460

FIG. 86



00822T" 00864260

FIG. 87A

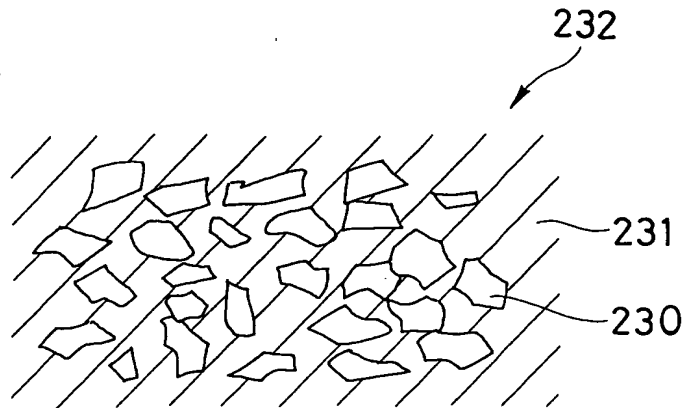


FIG. 87B

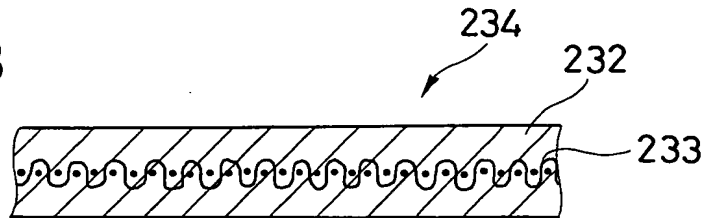
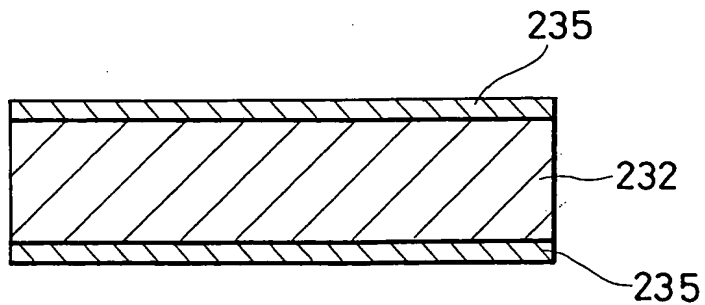


FIG. 87C



00822T" 00864260

FIG. 88A

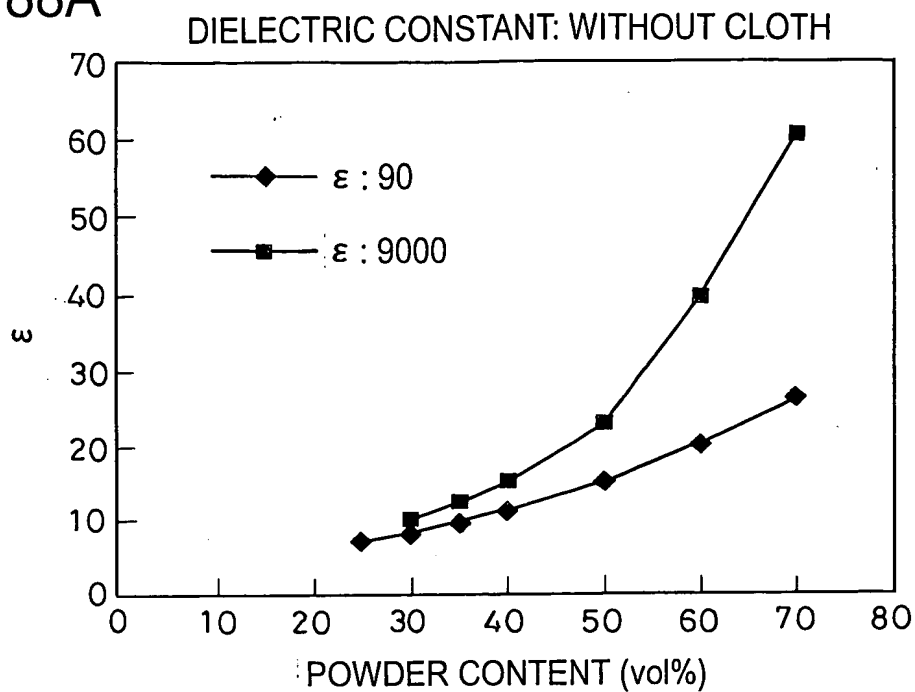


FIG. 88B

